

FIGURE 1A

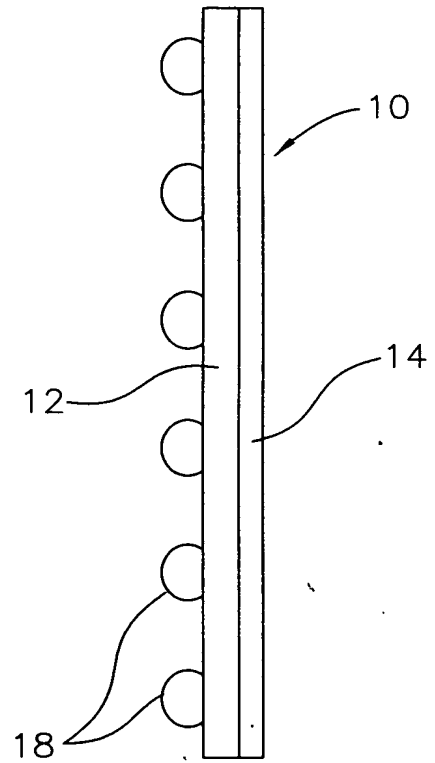


FIGURE 1B

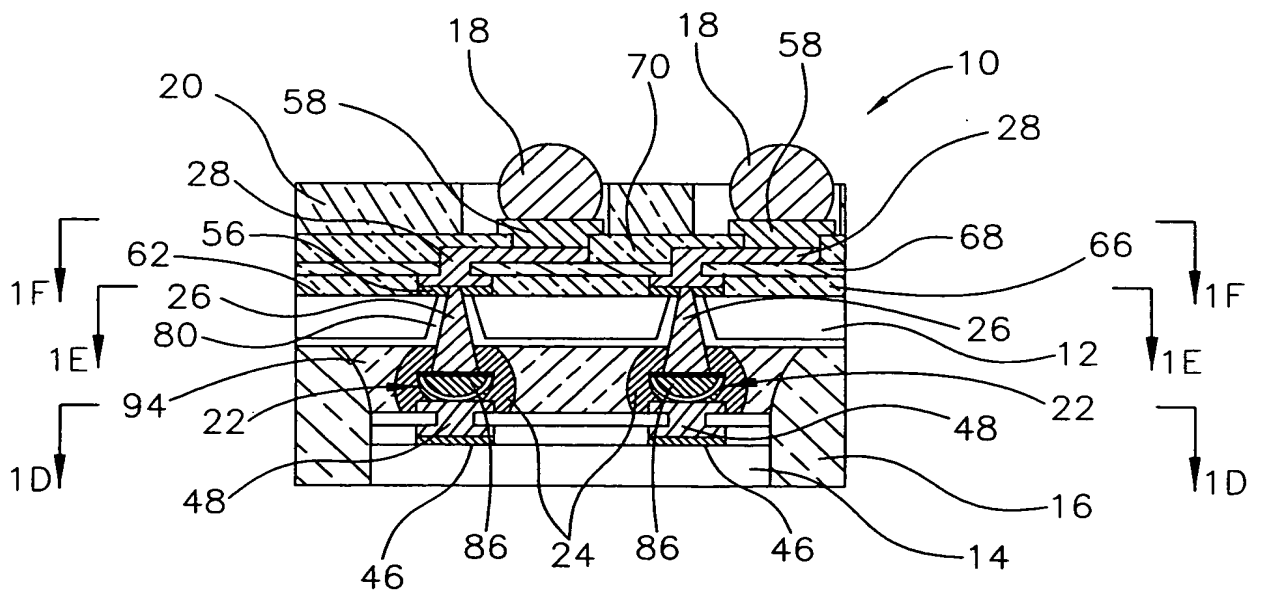


FIGURE 1C

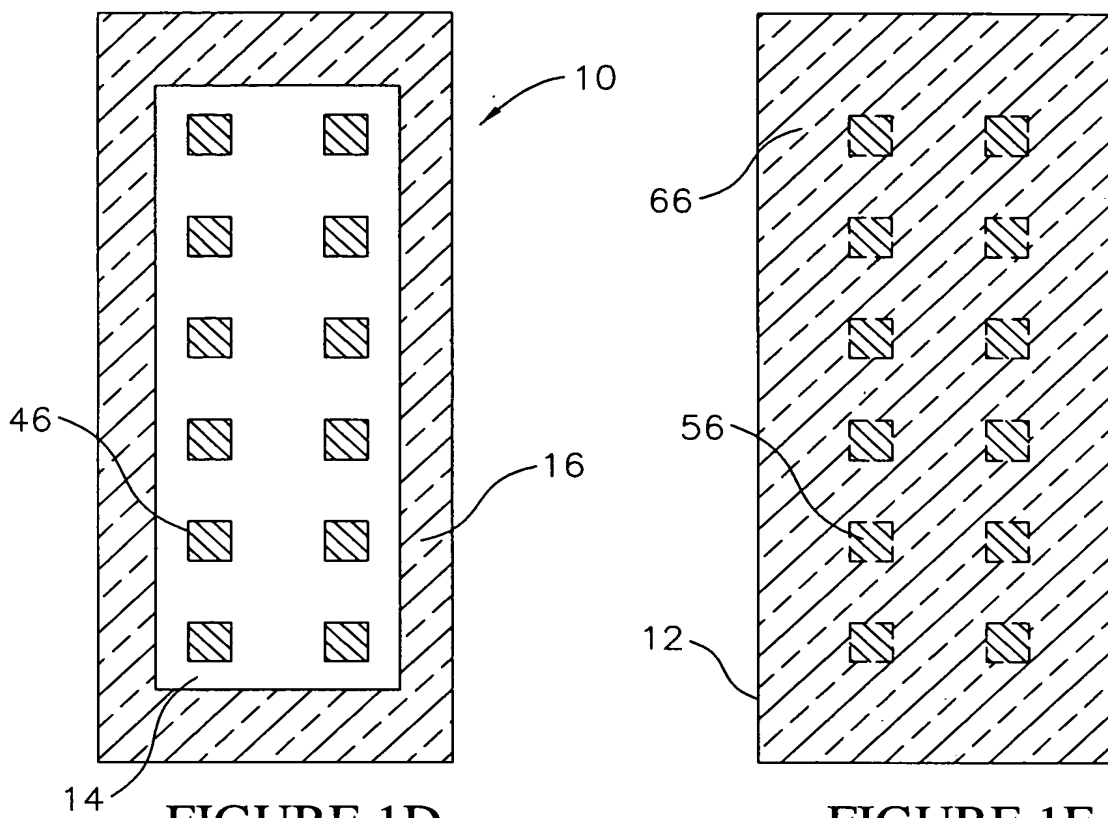


FIGURE 1D

FIGURE 1E

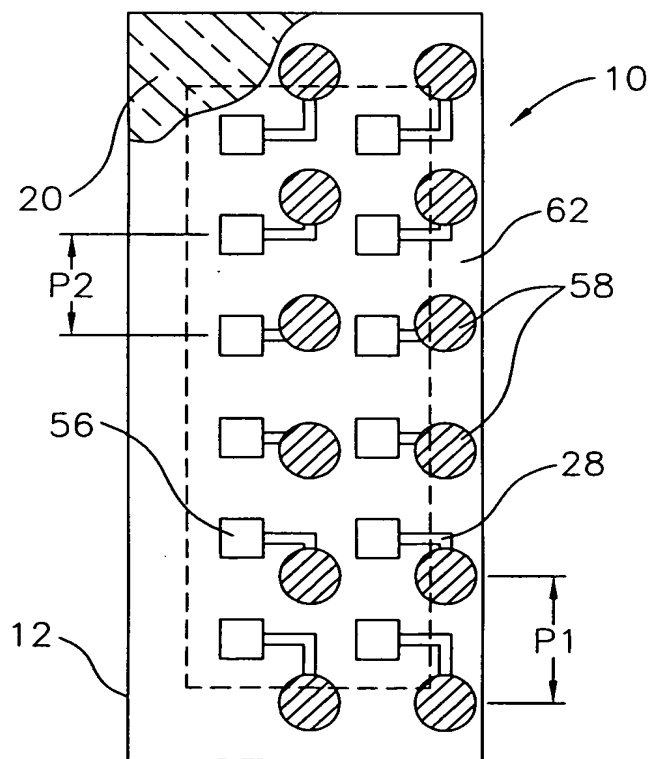


FIGURE 1F

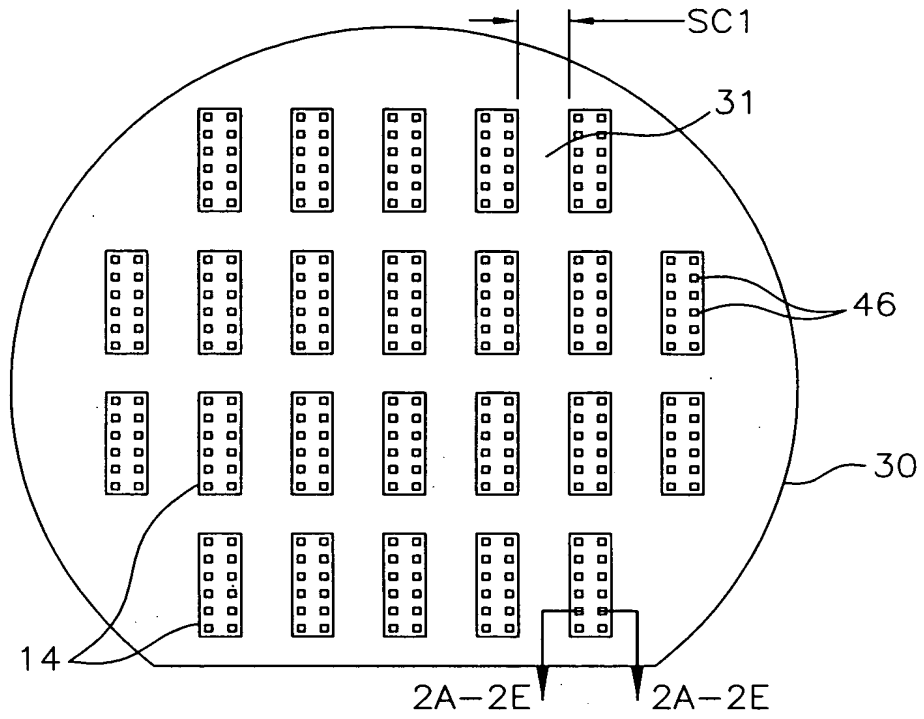


FIGURE 2

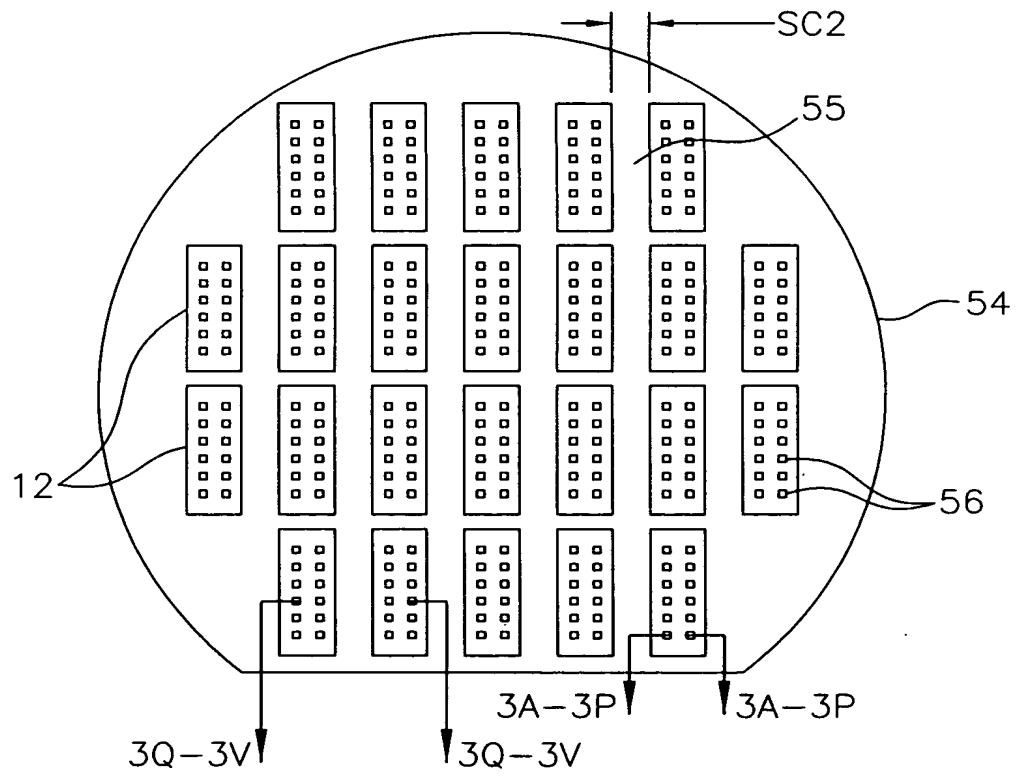


FIGURE 3

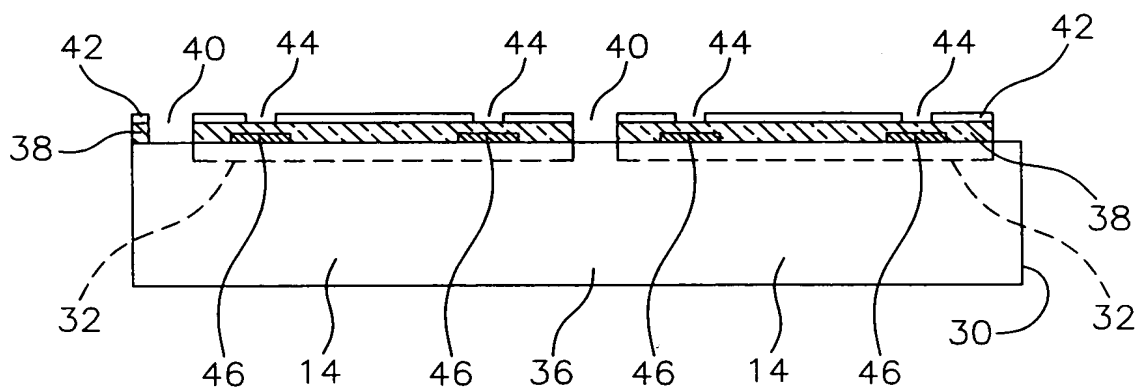


FIGURE 2A

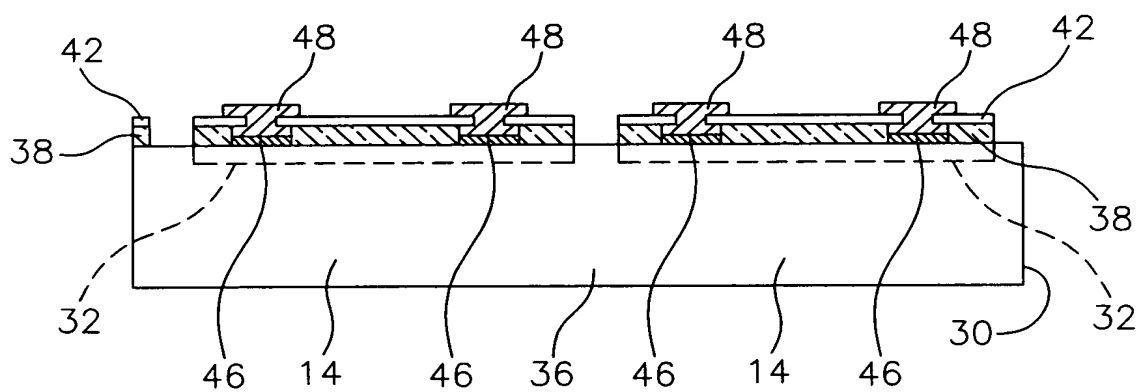


FIGURE 2B

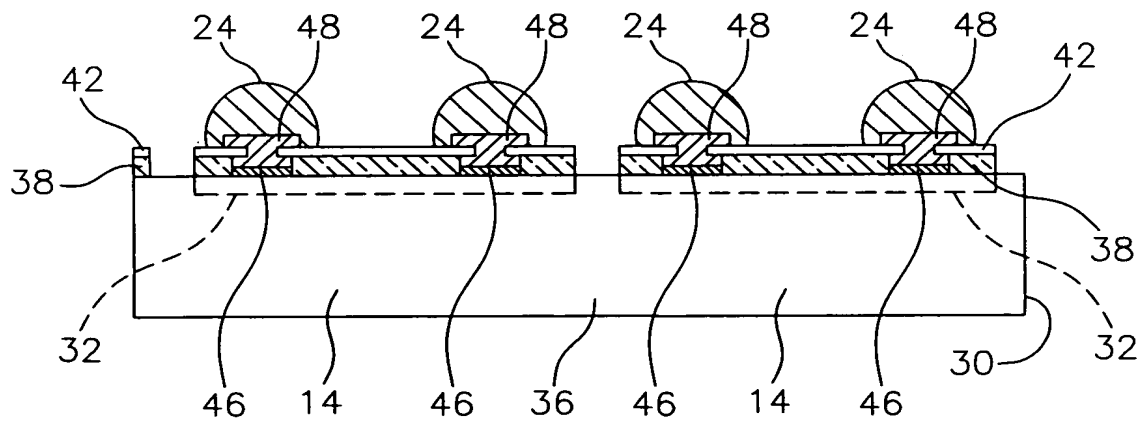


FIGURE 2C

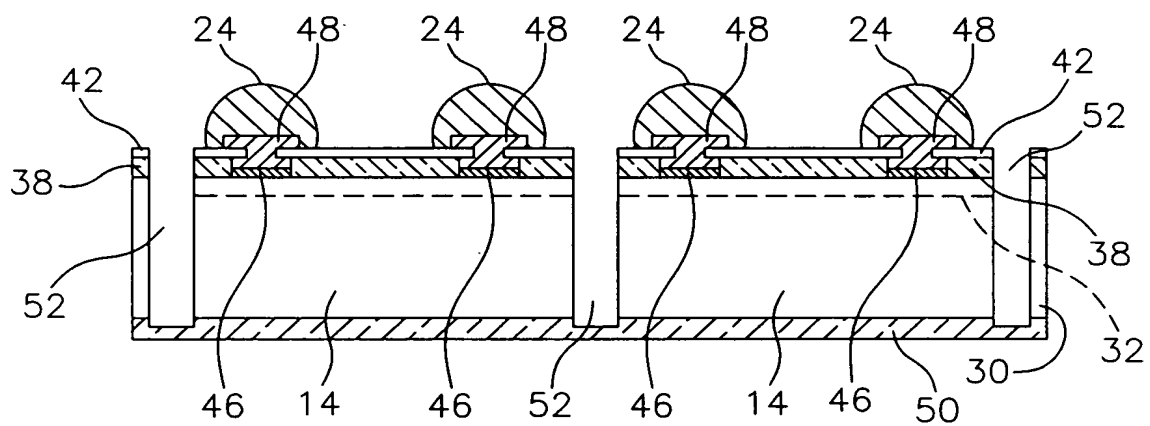


FIGURE 2D

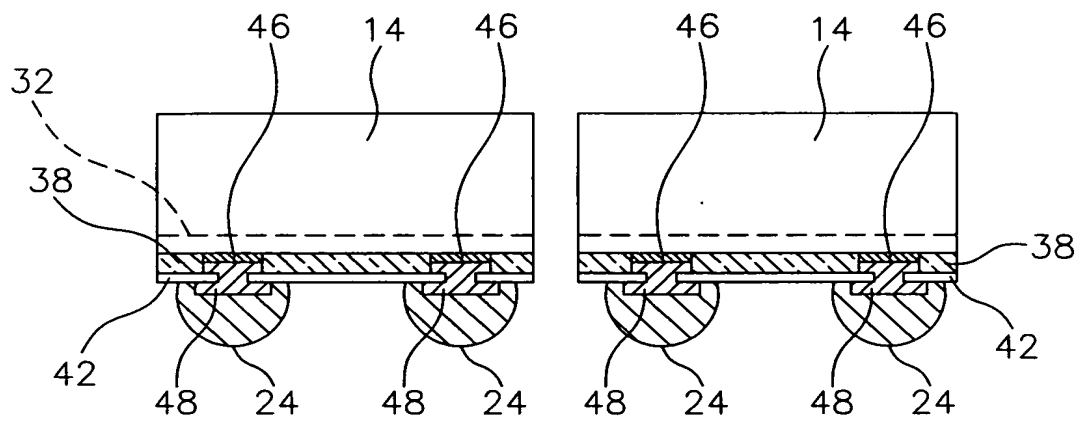


FIGURE 2E

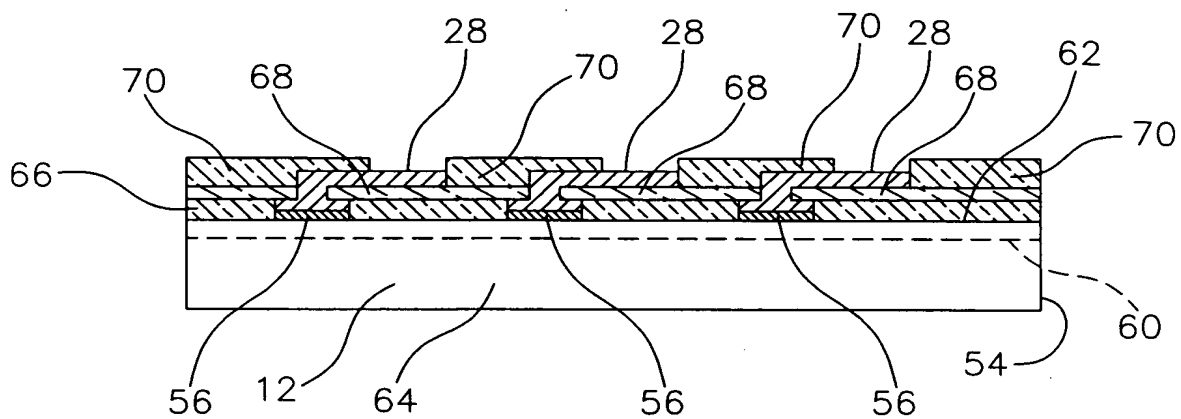


FIGURE 3A

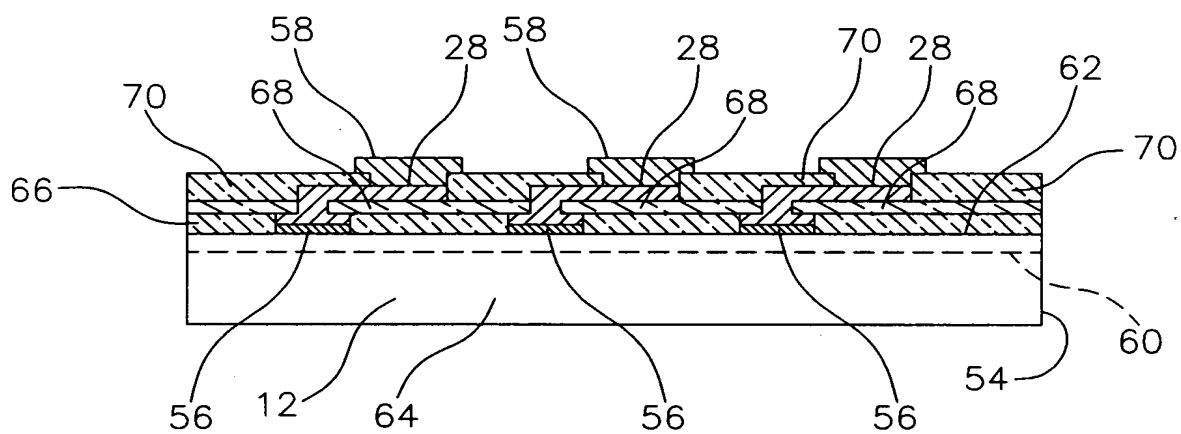


FIGURE 3B

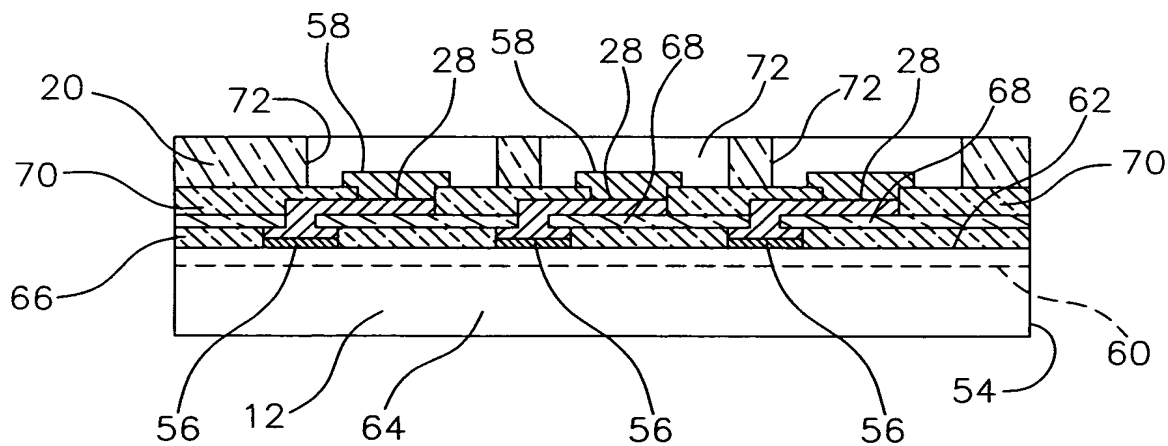


FIGURE 3C

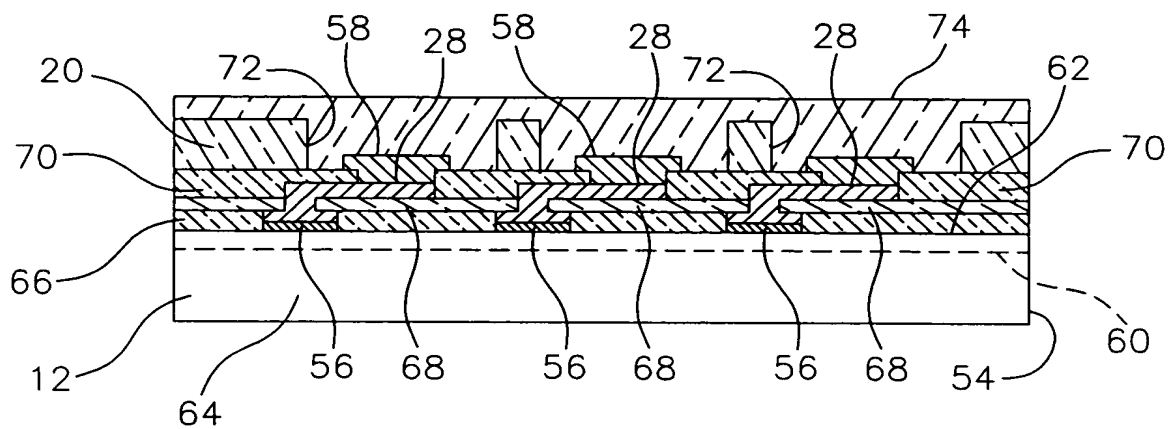


FIGURE 3D

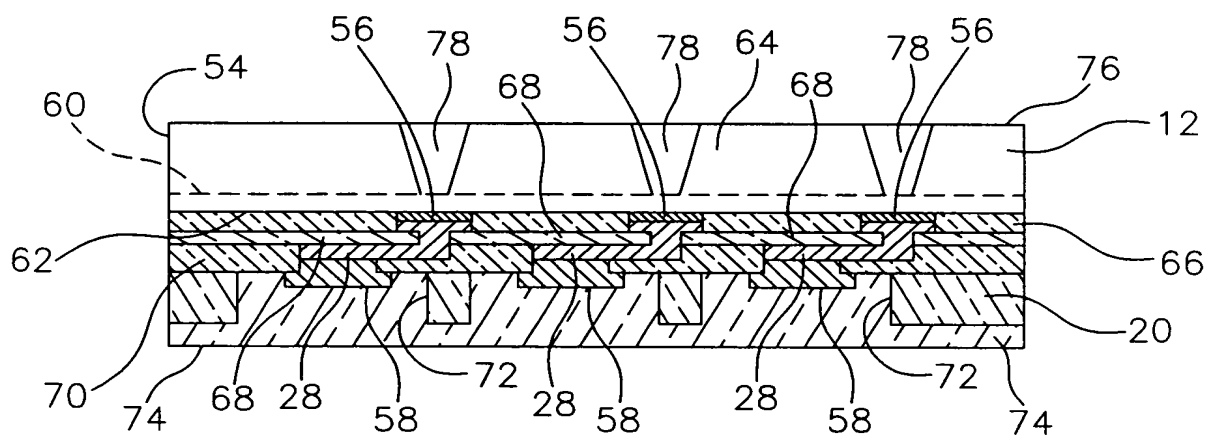


FIGURE 3E

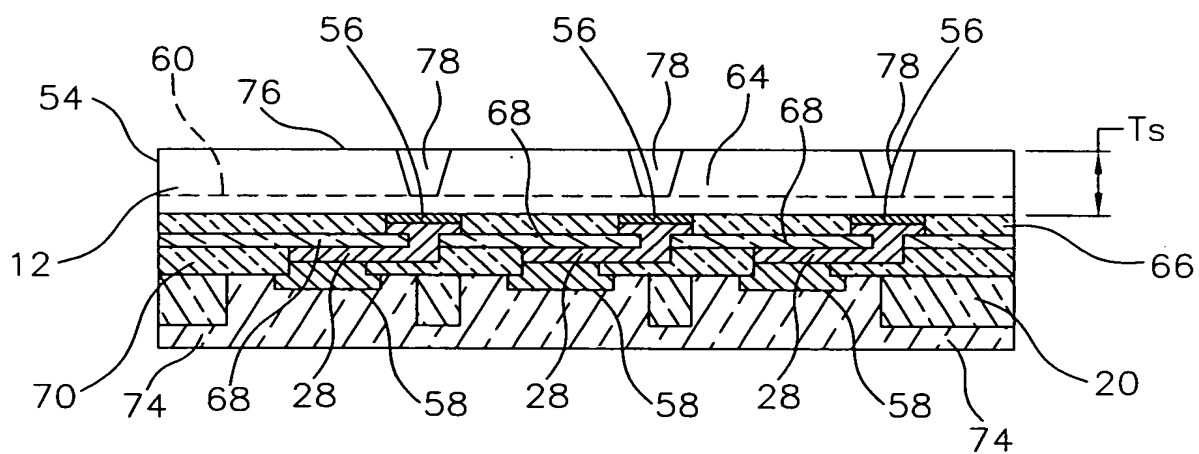


FIGURE 3F

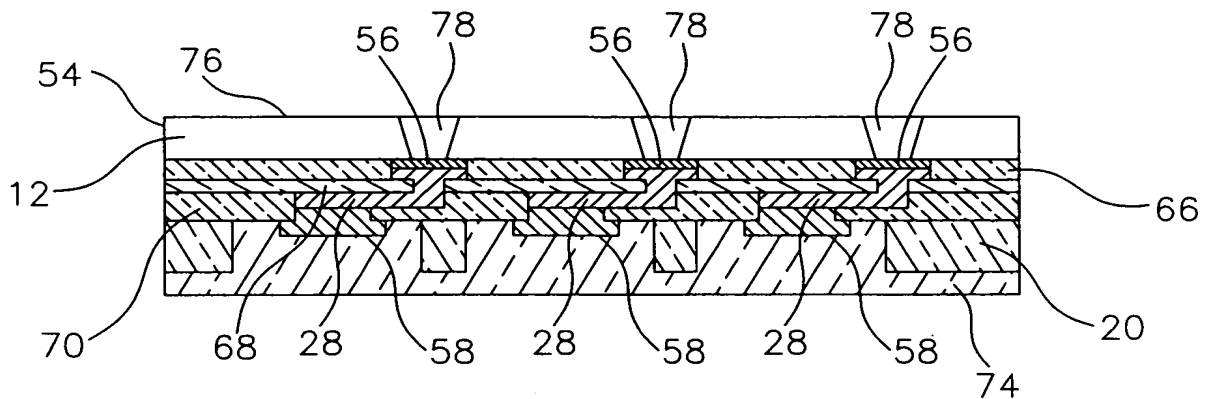


FIGURE 3G

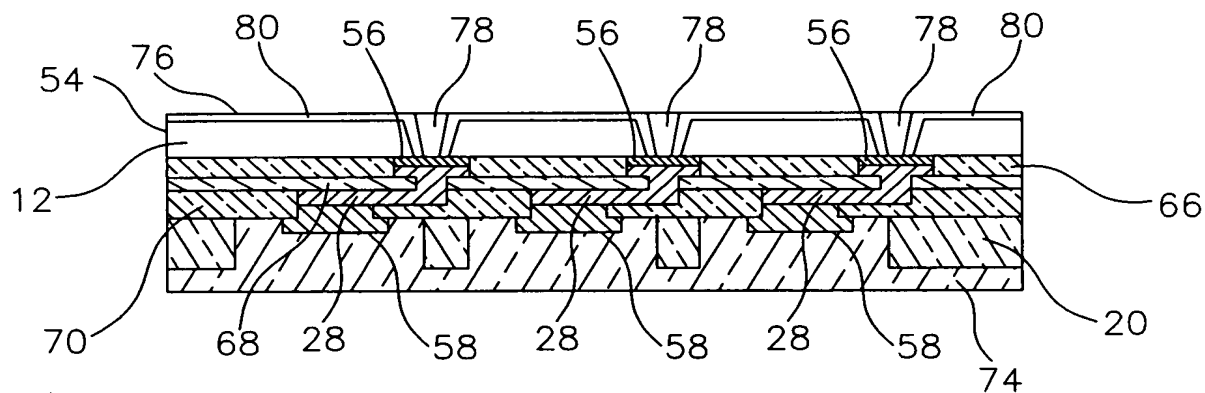


FIGURE 3H

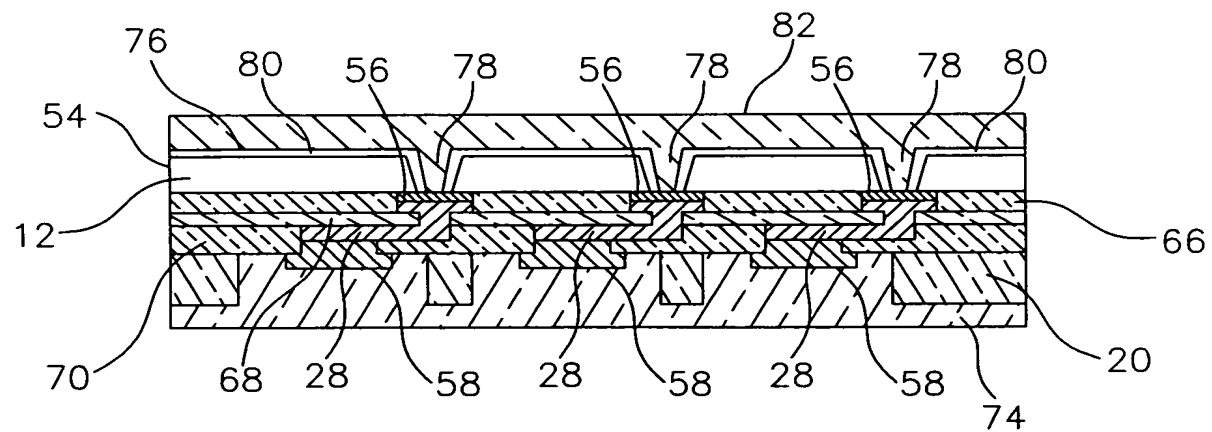


FIGURE 3I

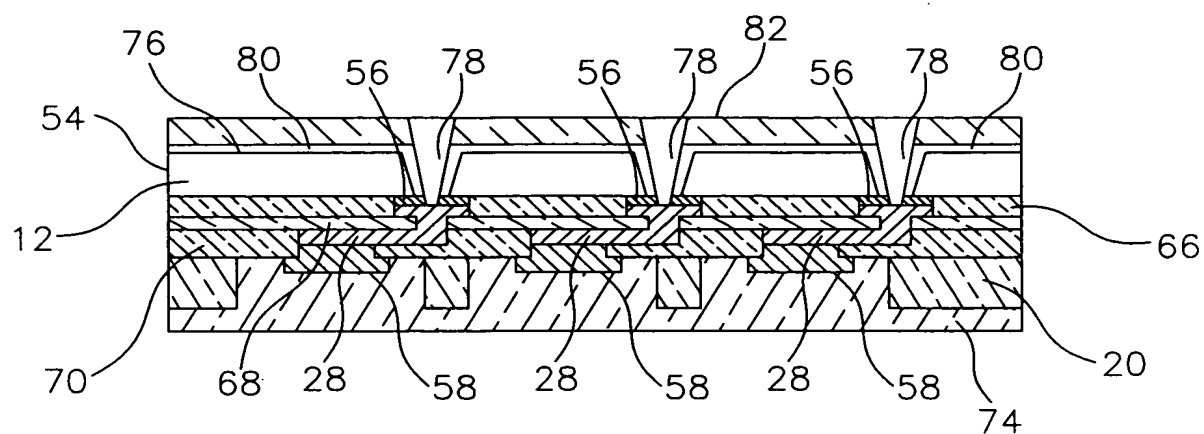


FIGURE 3J

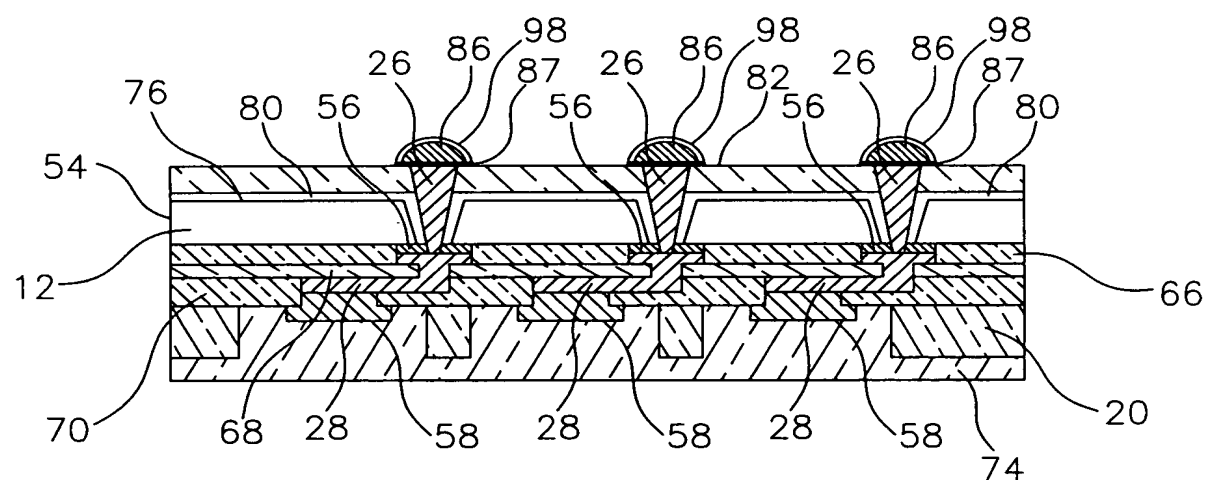


FIGURE 3K

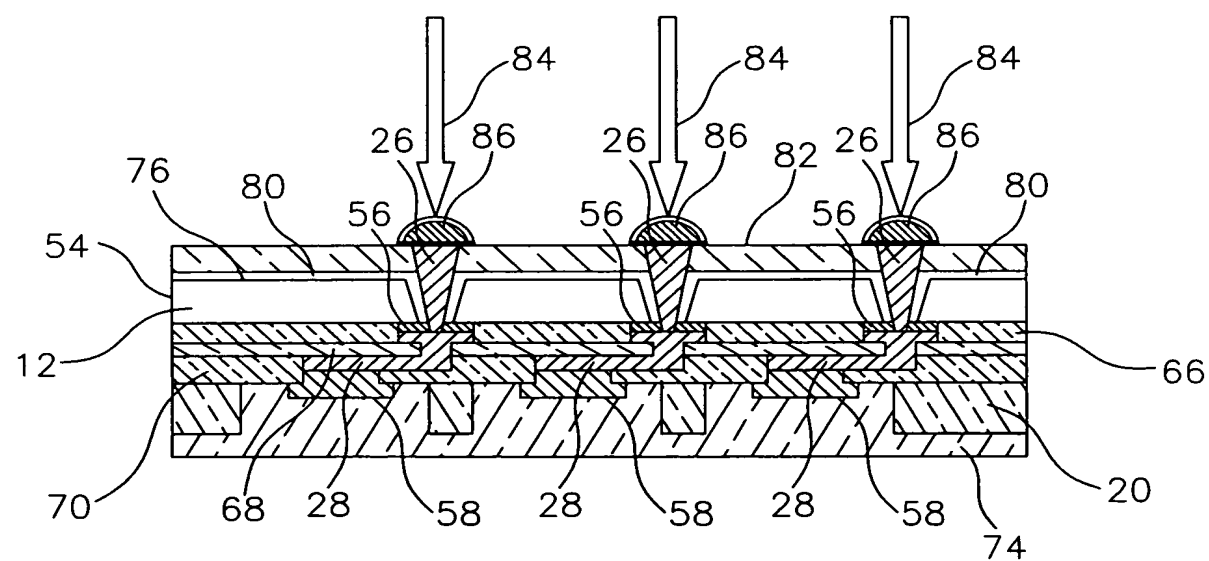
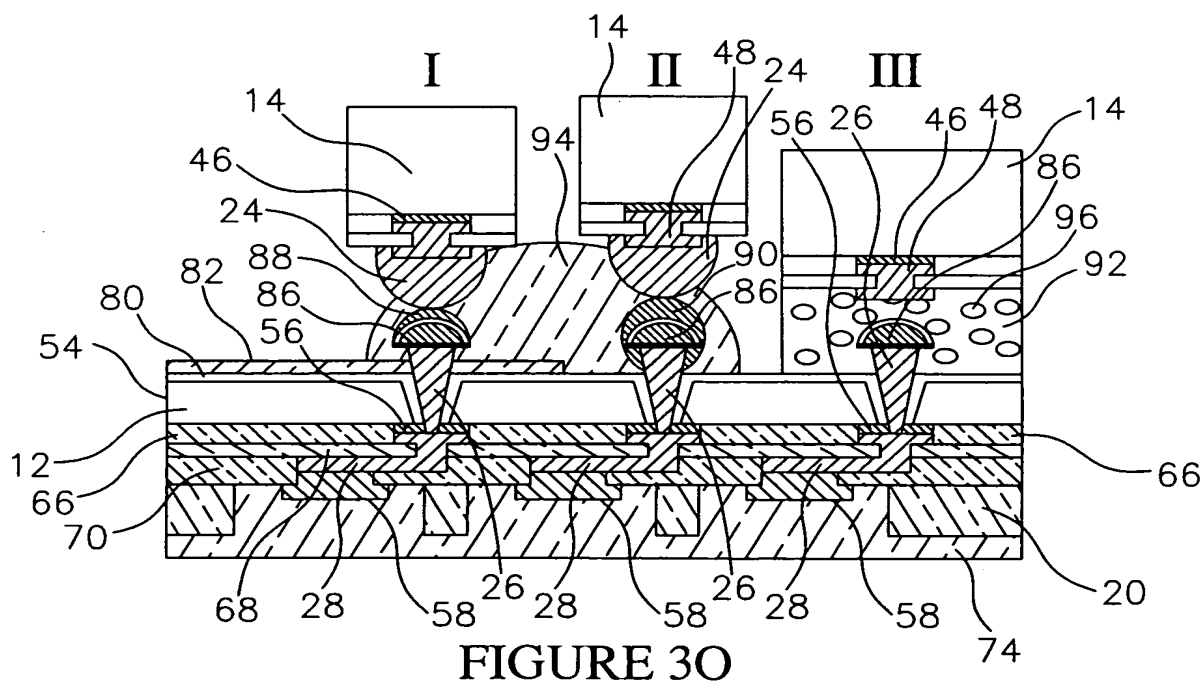
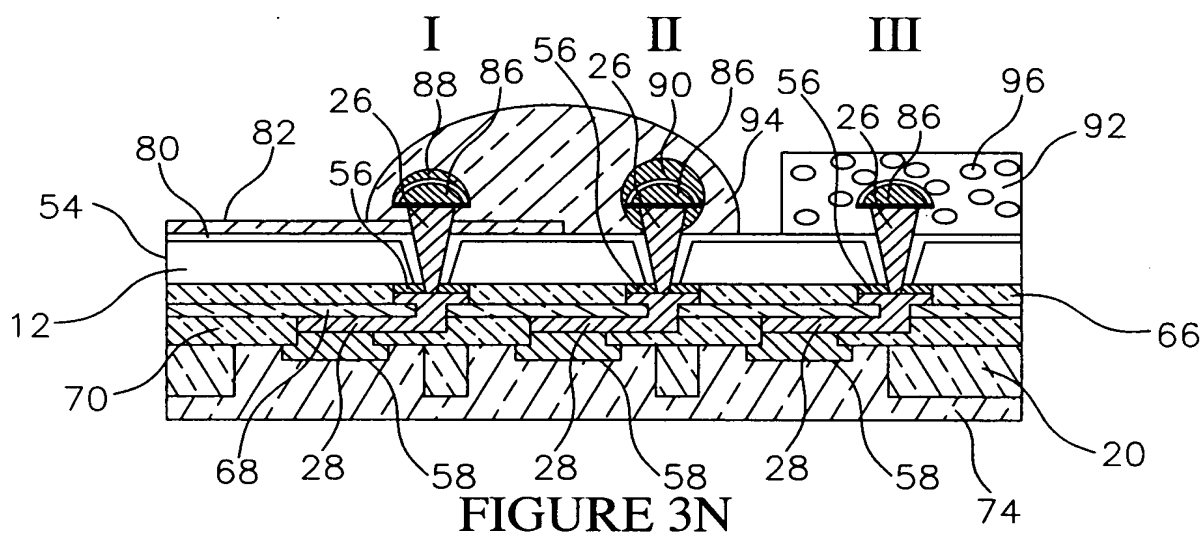
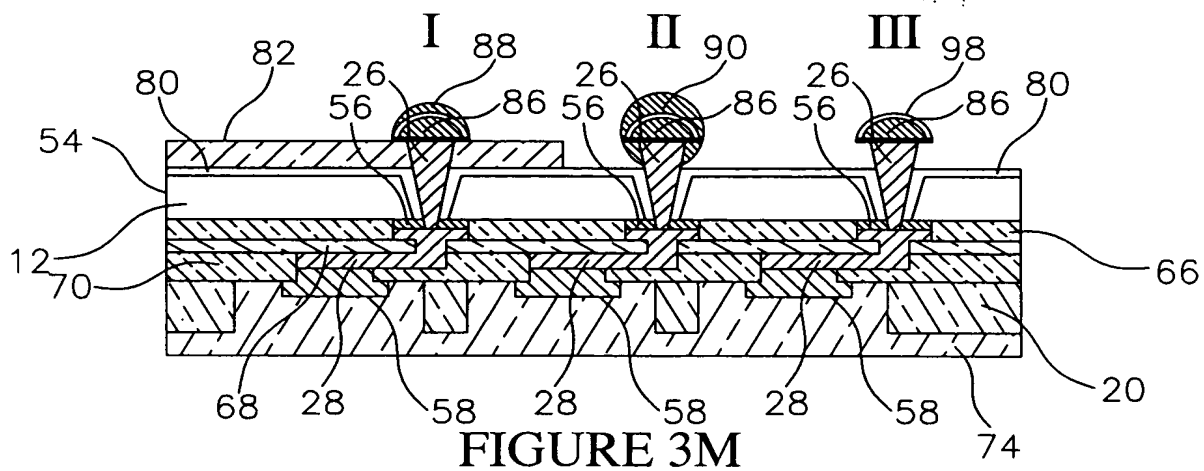
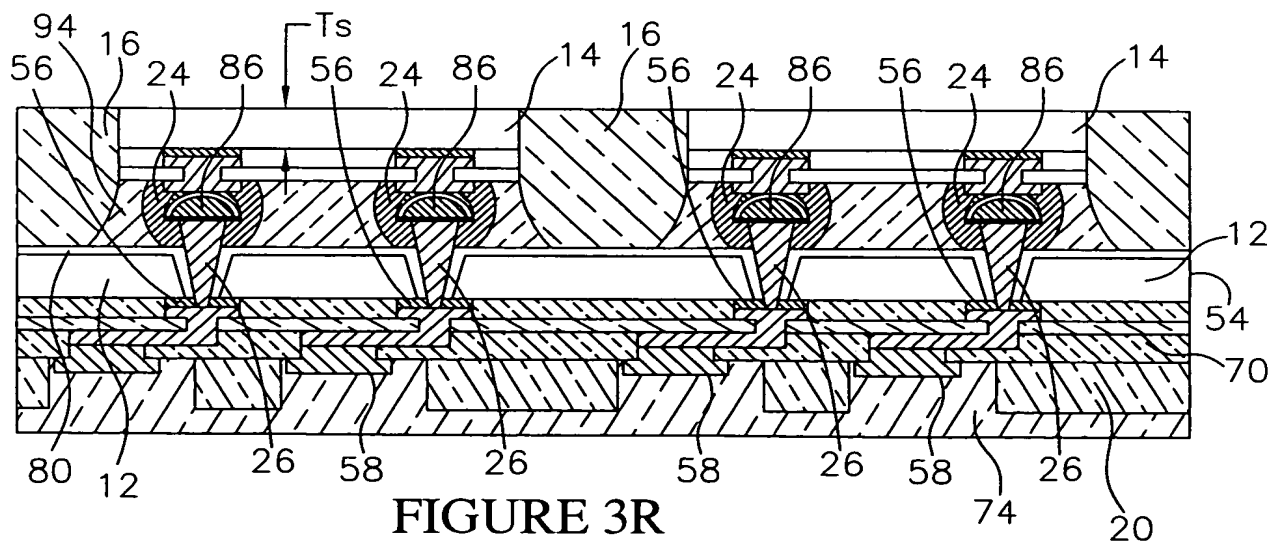
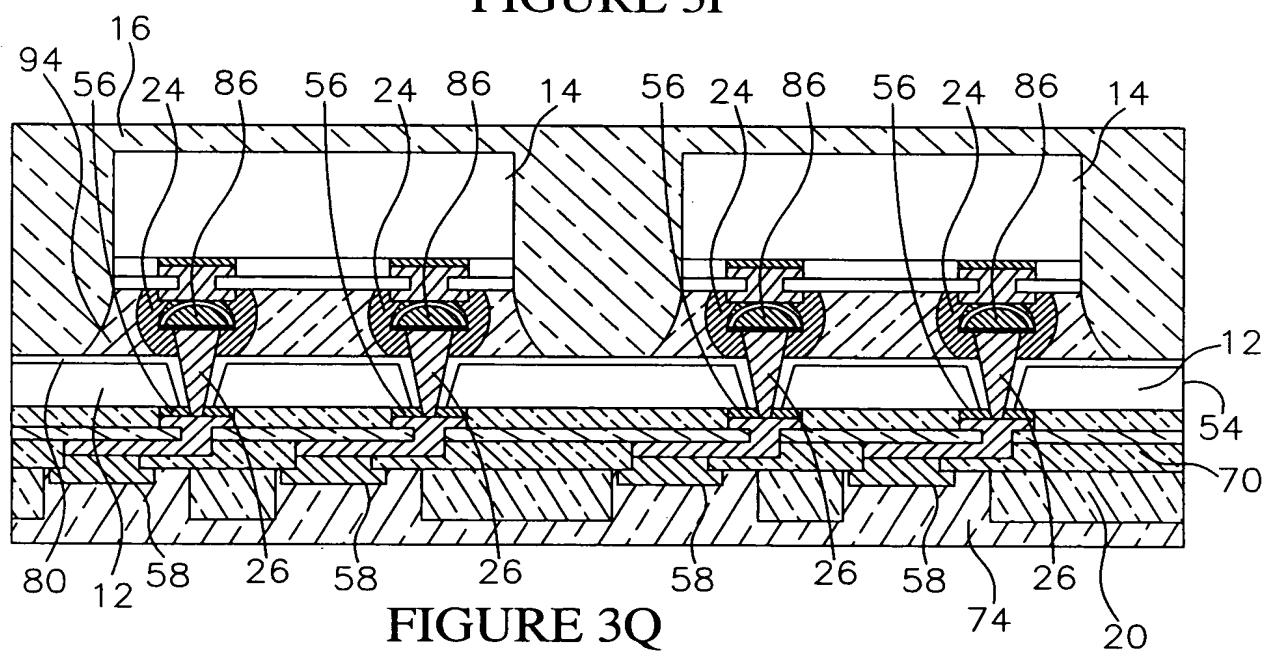
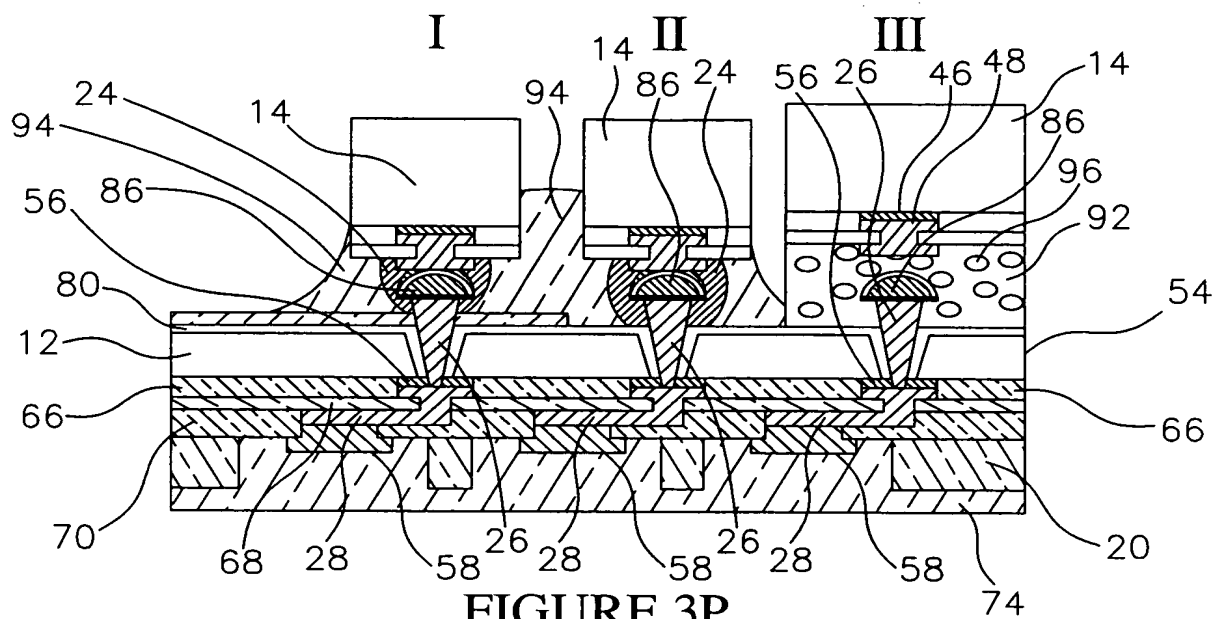
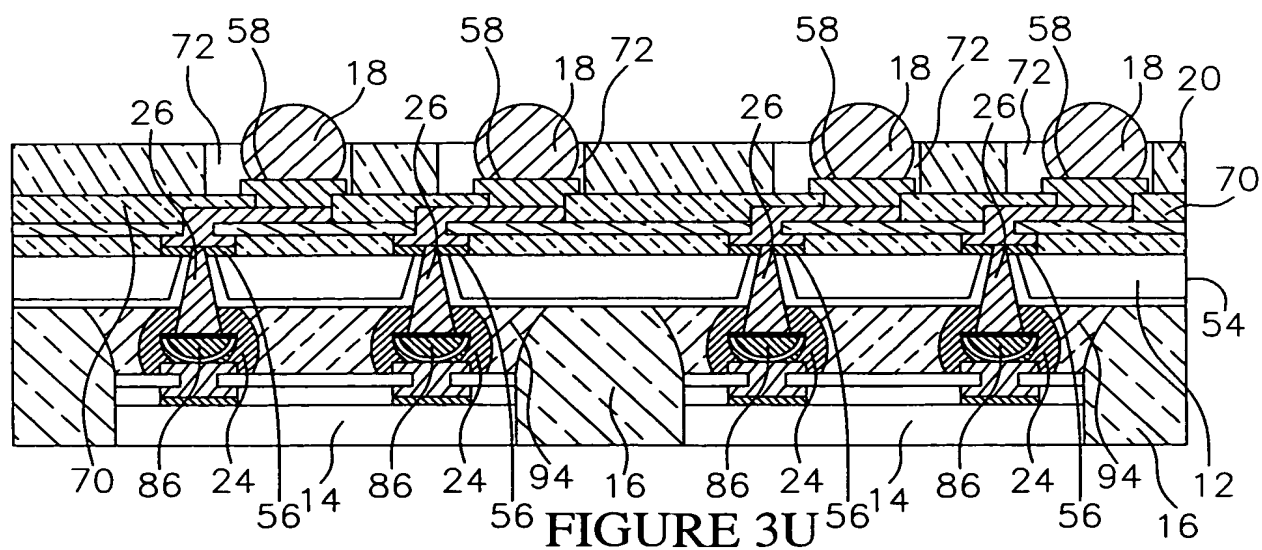
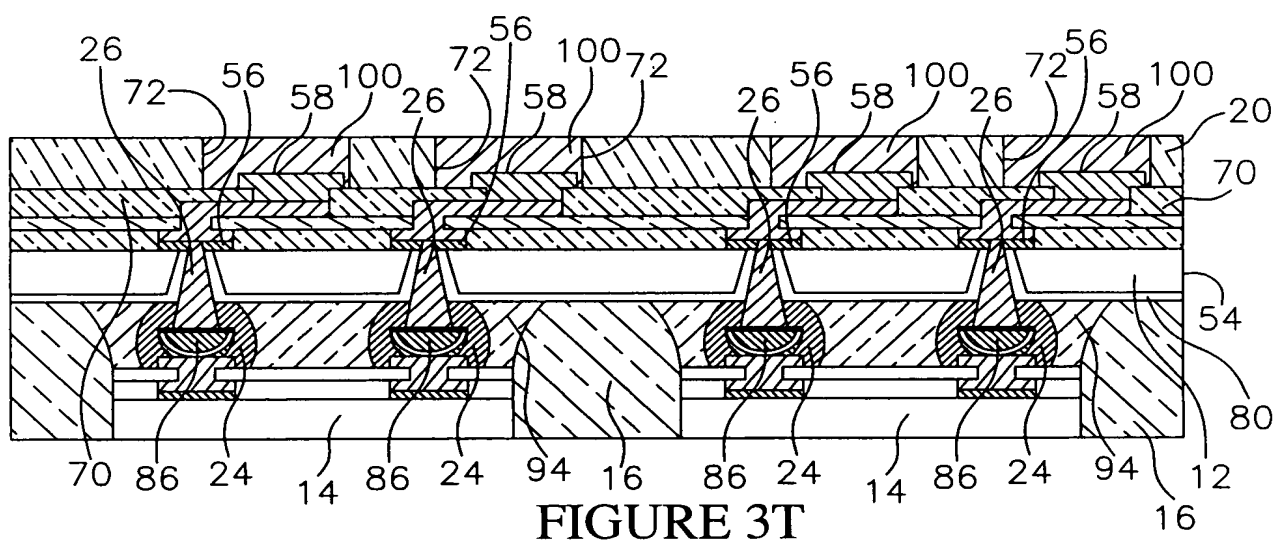
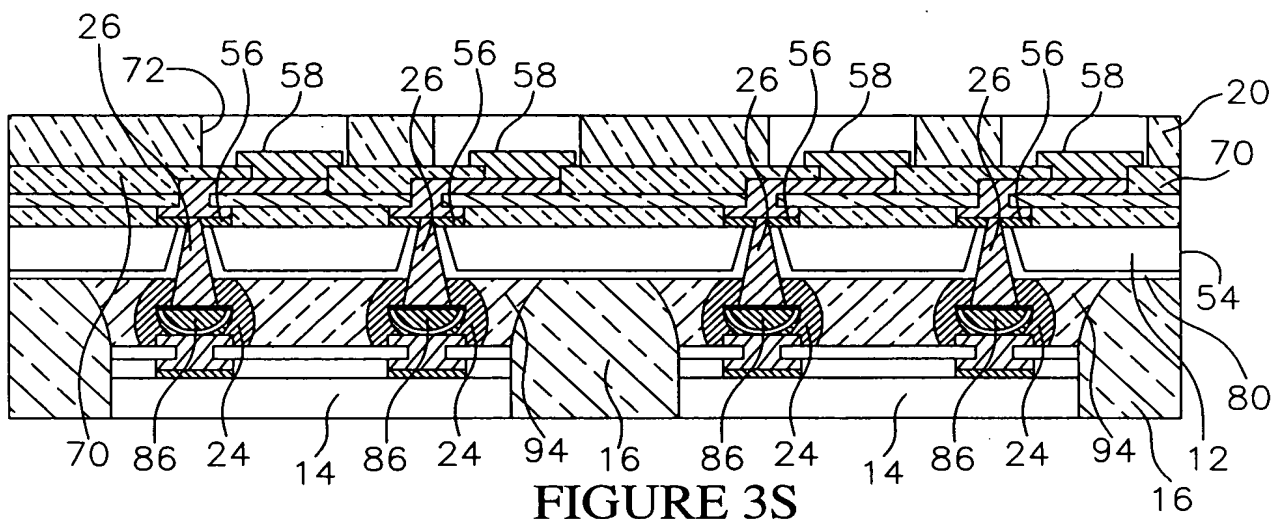


FIGURE 3L







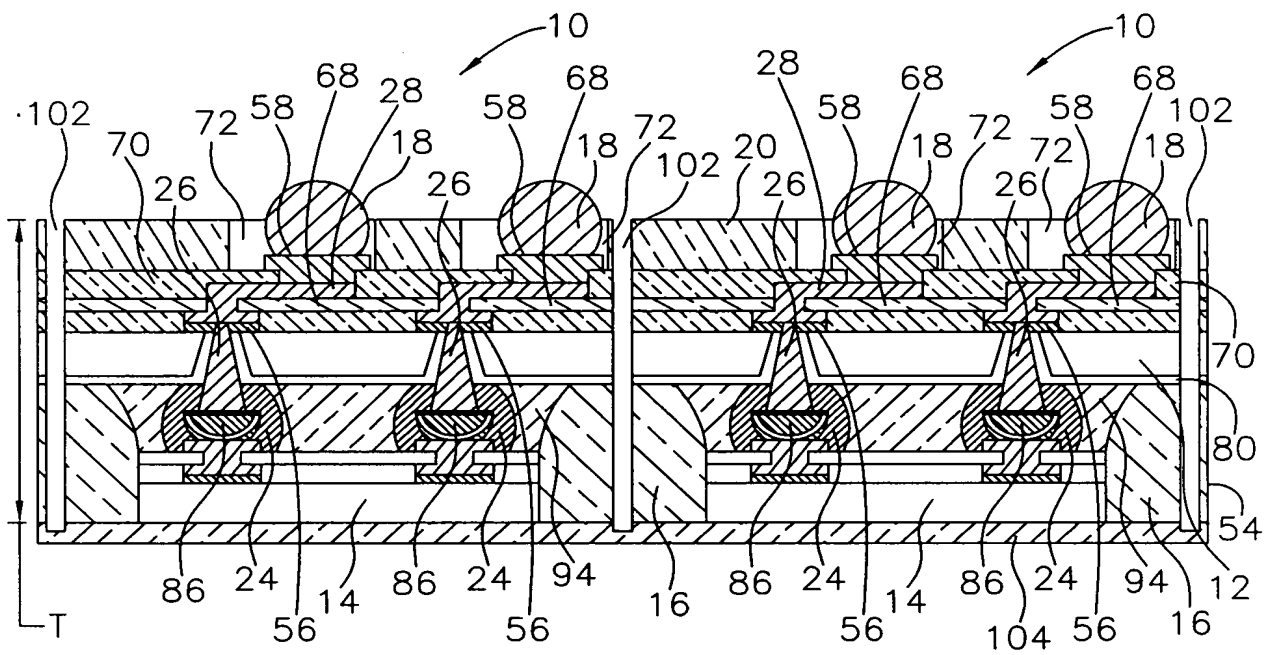


FIGURE 3V

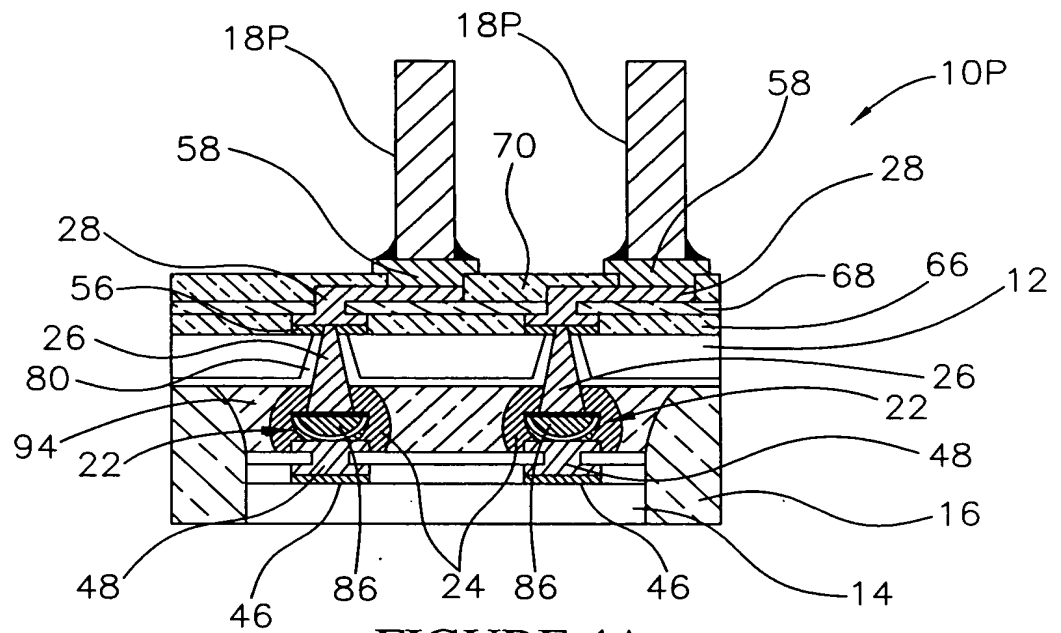


FIGURE 4A

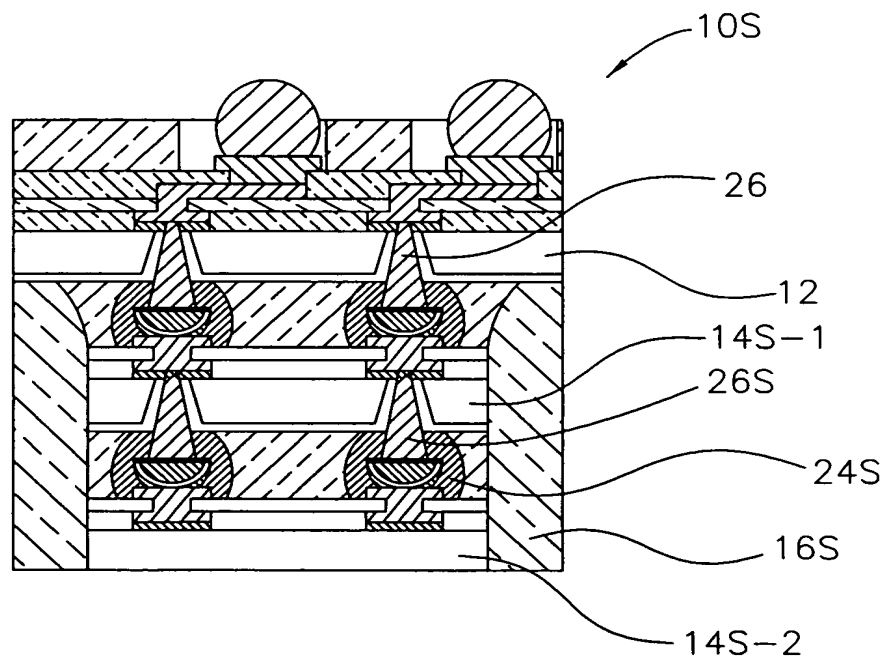


FIGURE 4B

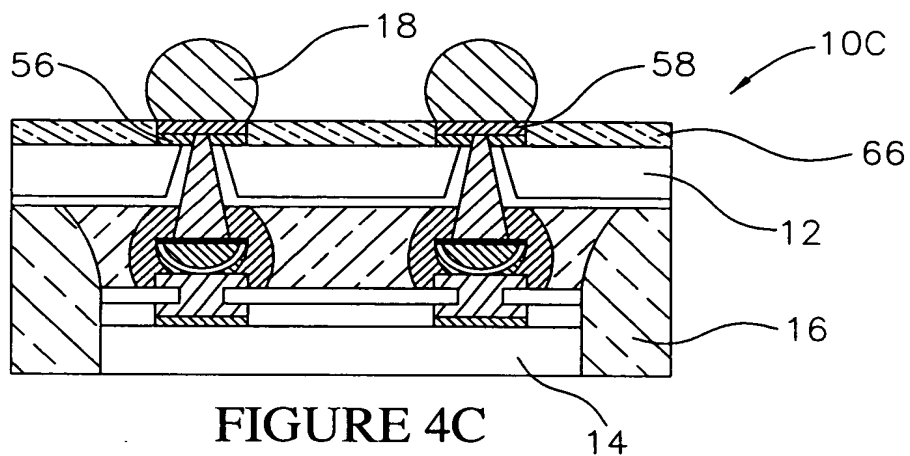


FIGURE 4C

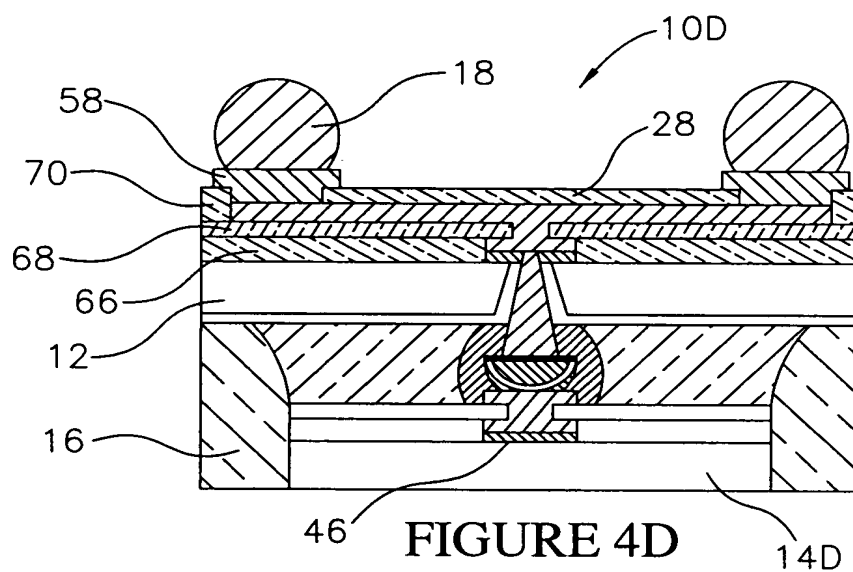


FIGURE 4D

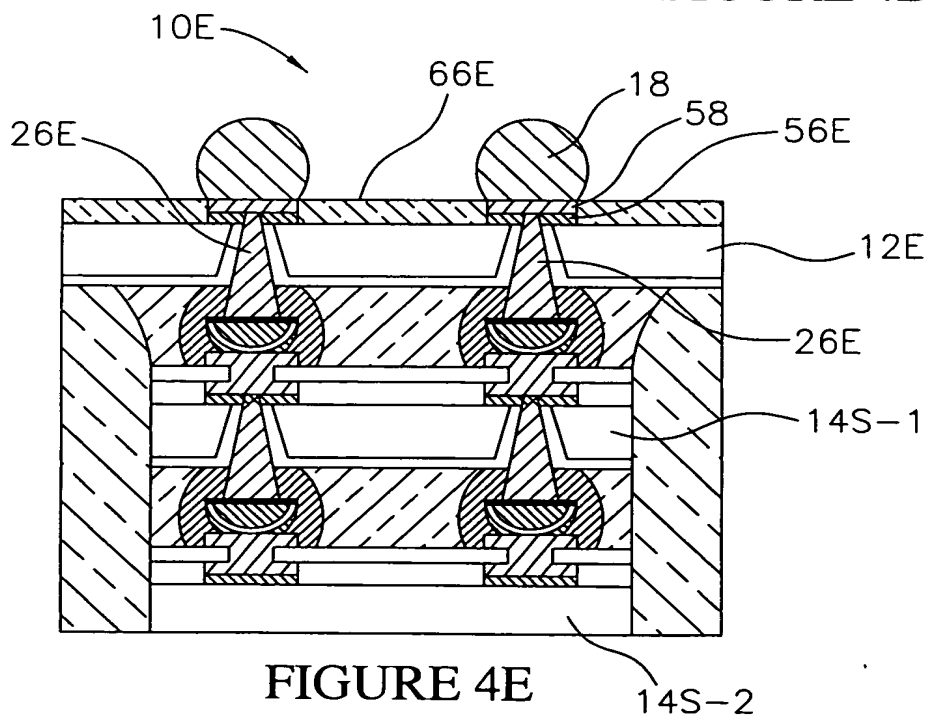


FIGURE 4E

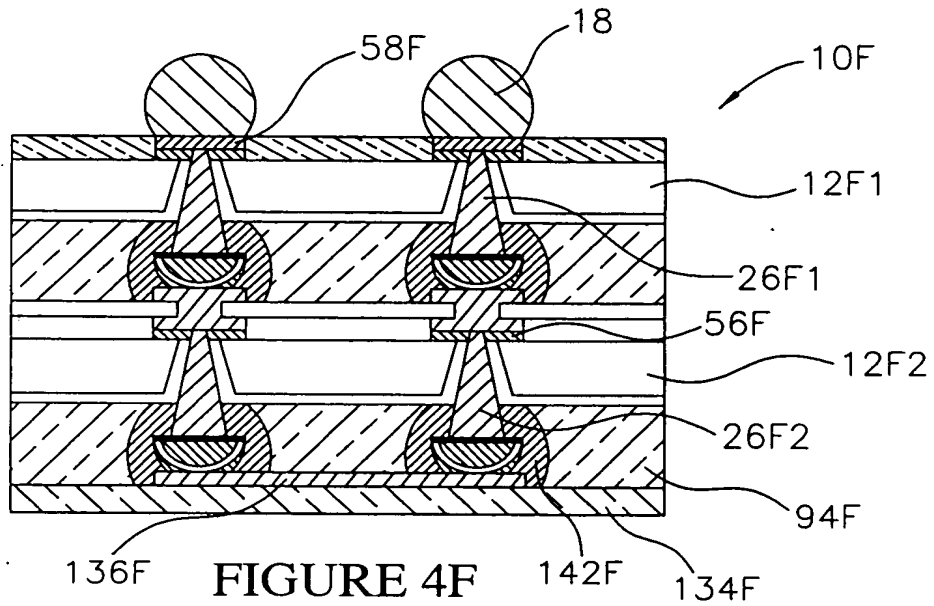


FIGURE 4F

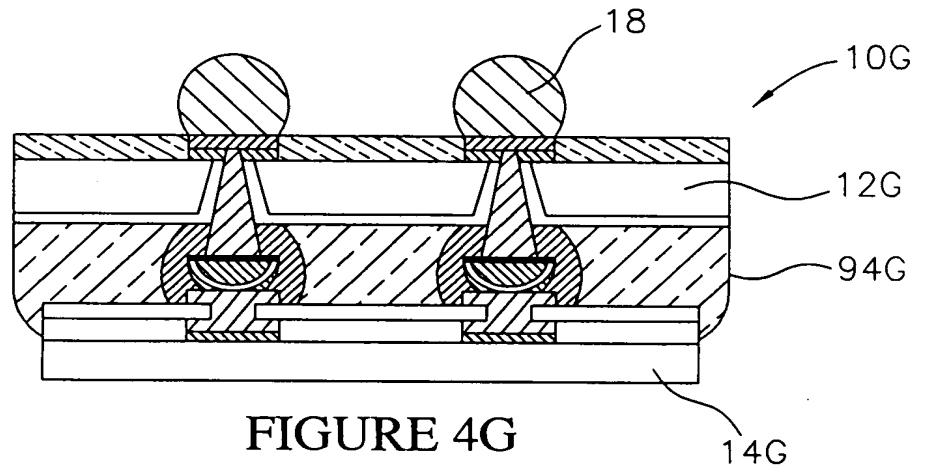


FIGURE 4G

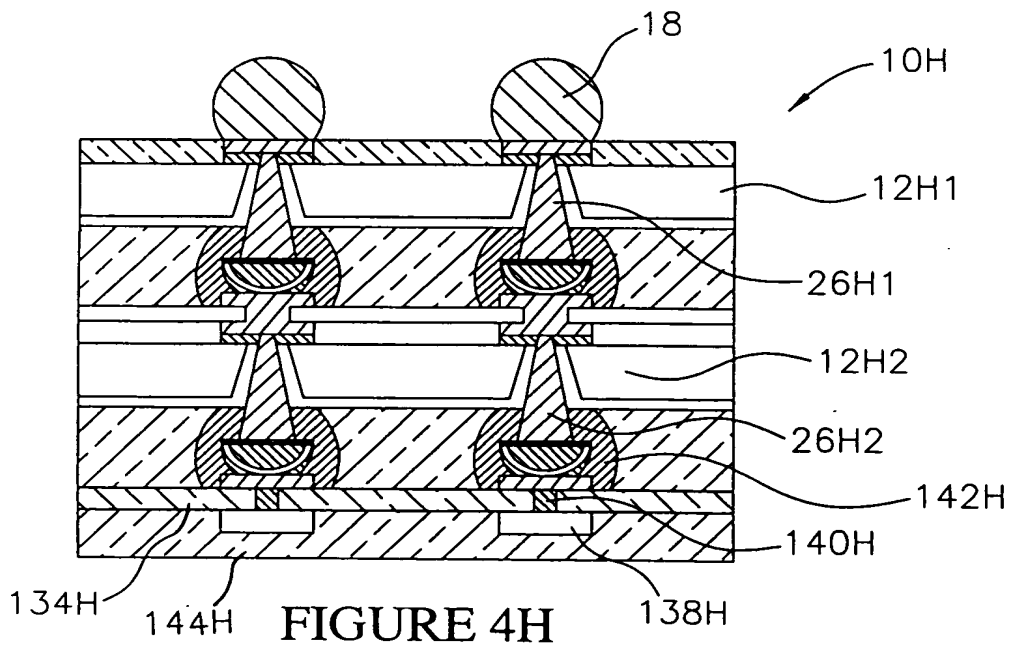


FIGURE 4H

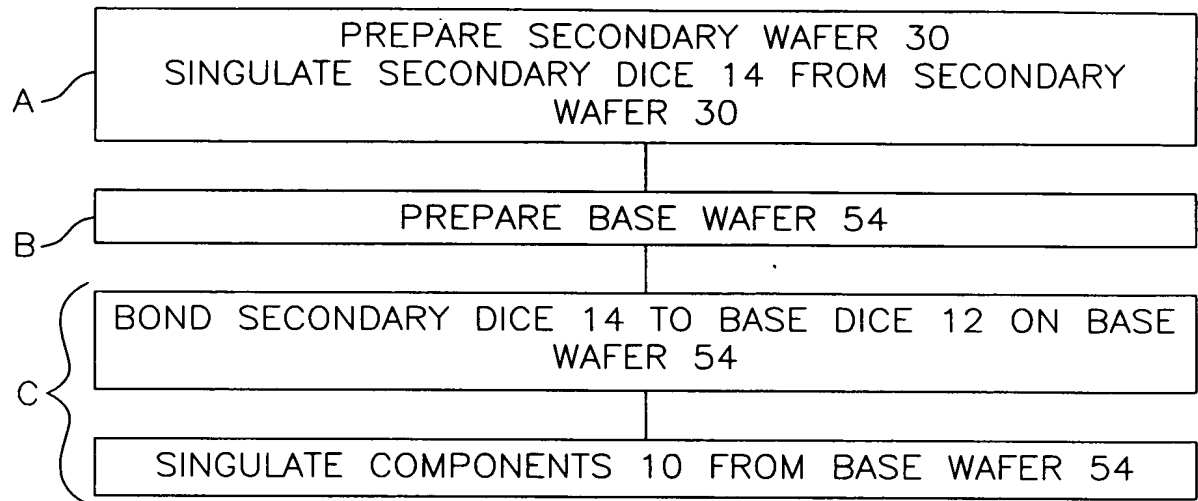


FIGURE 5A

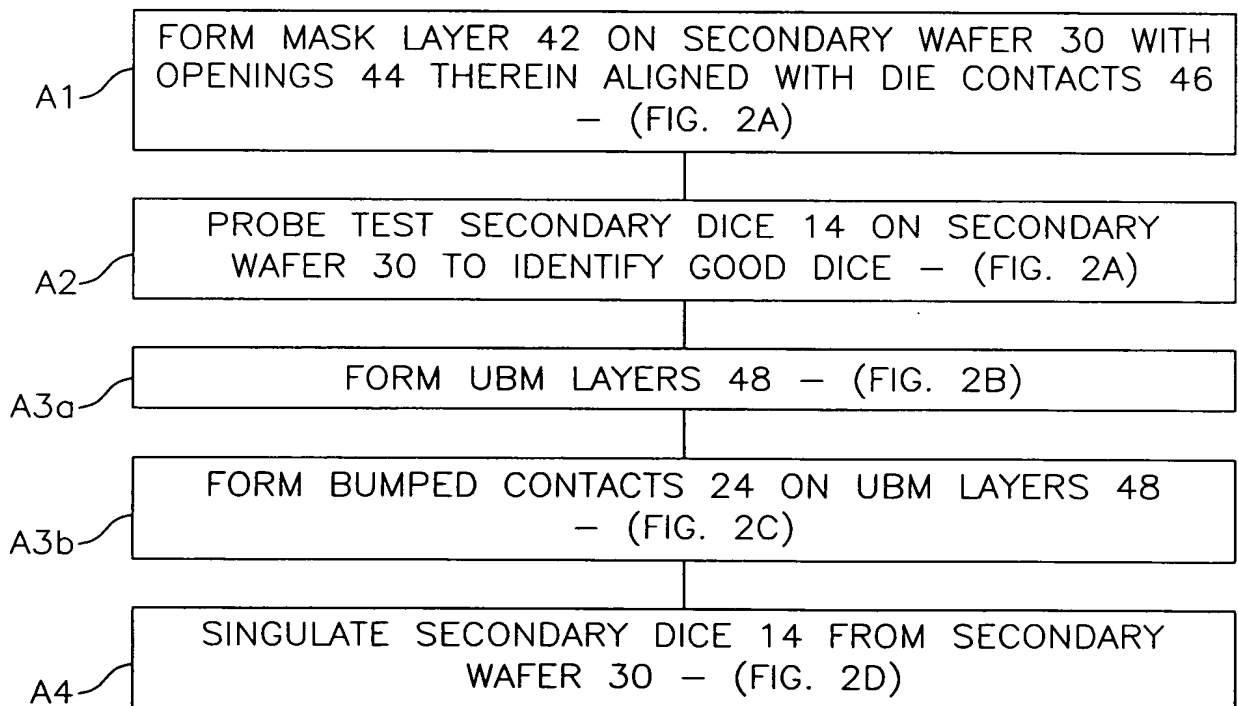


FIGURE 5B

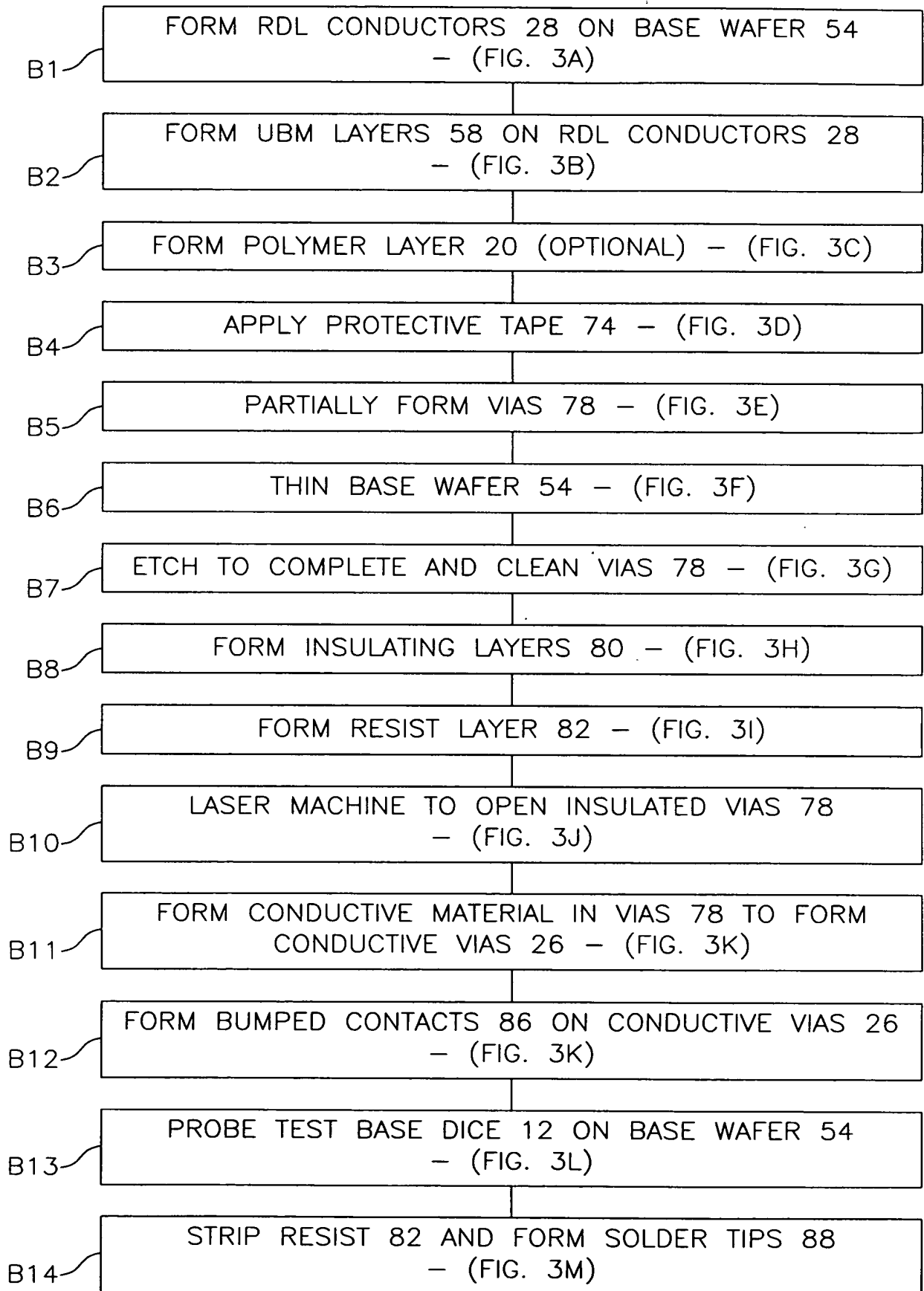


FIGURE 5C

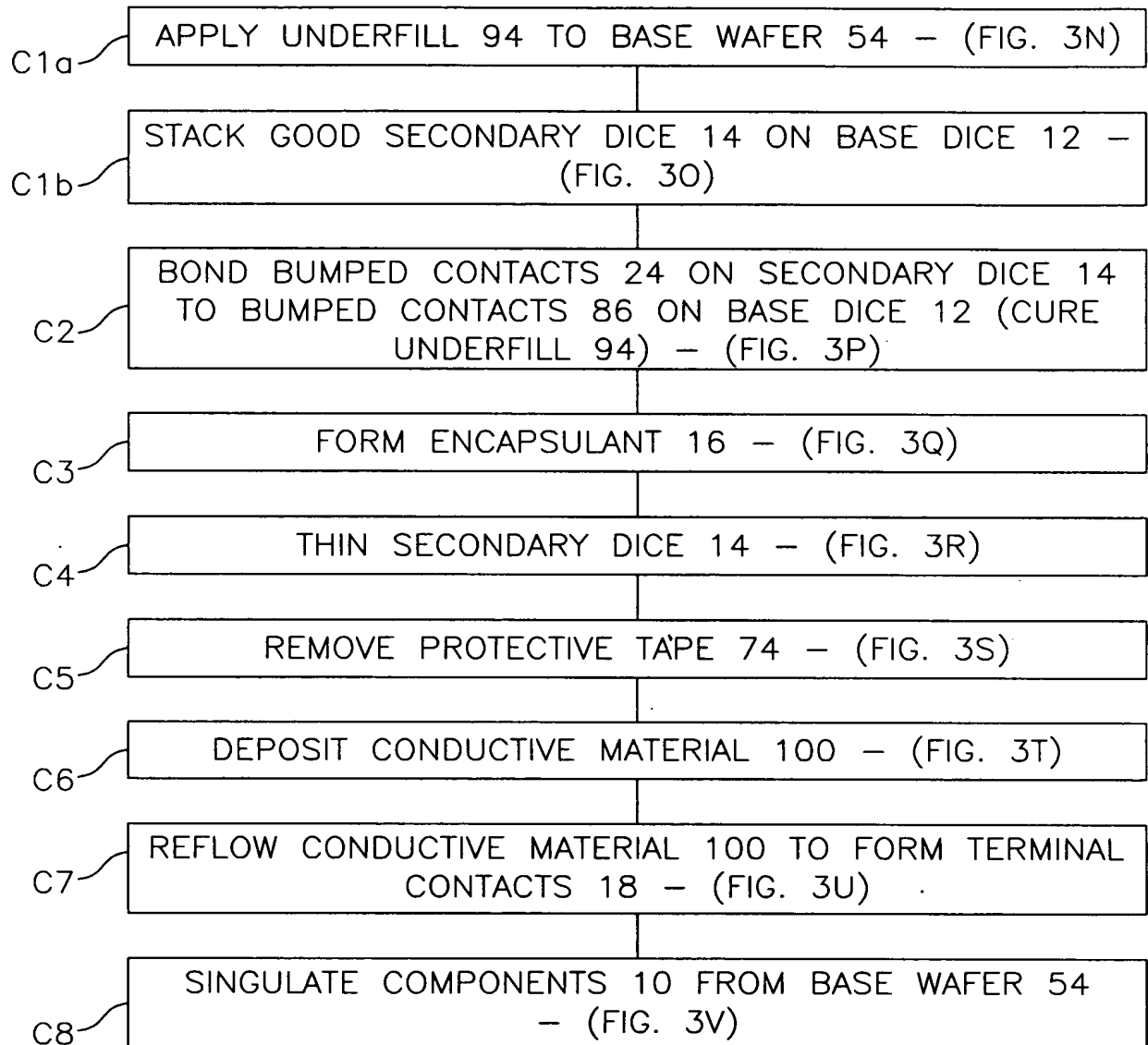


FIGURE 5D

MINISCUS BUMP/FLIP CHIP BONDER (M8)

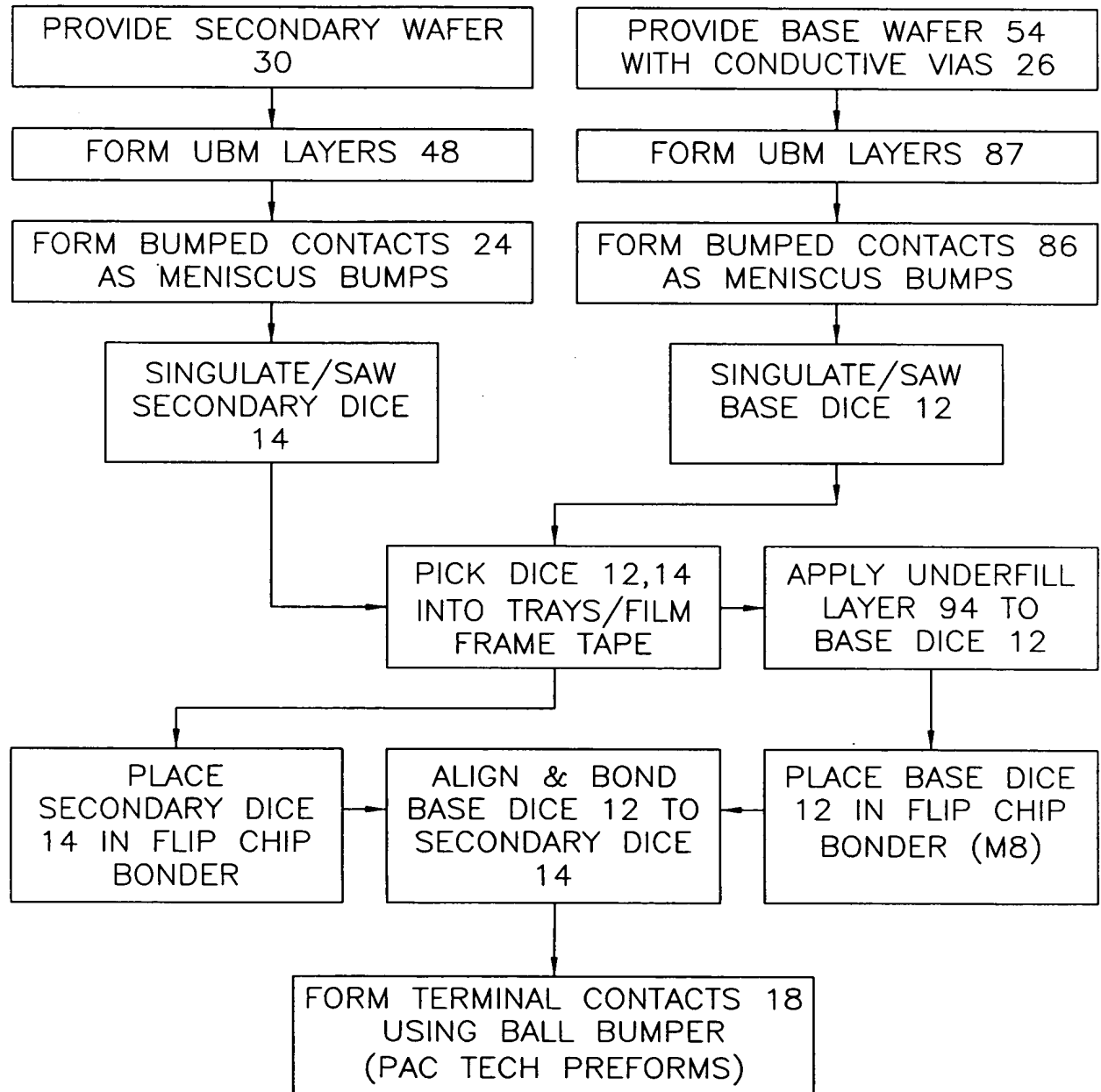


FIGURE 6A

BALL BUMPER (PAC TECH 80um)/FLIP CHIP BONDER (M8)

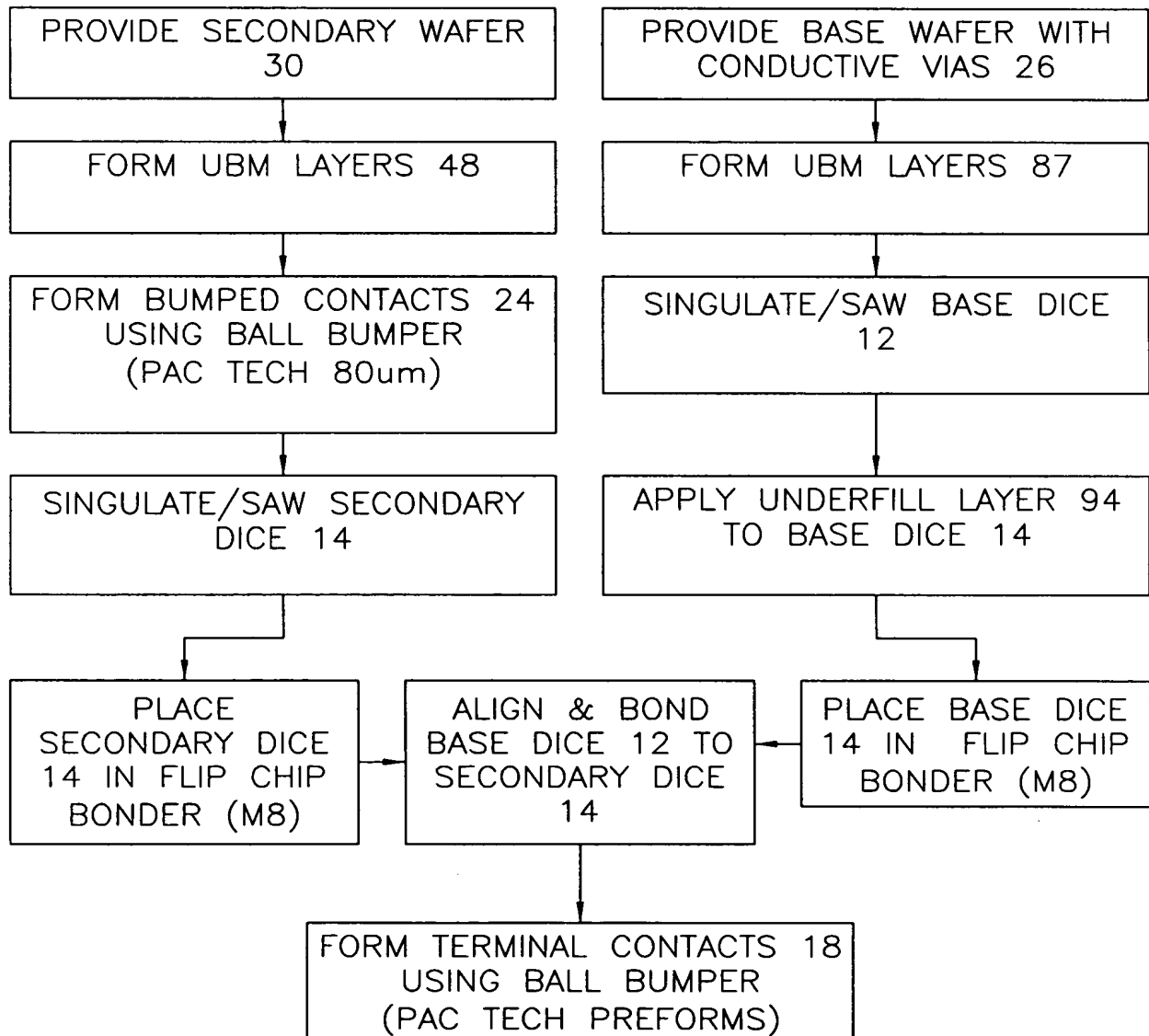


FIGURE 6B

BALL BUMPER (PAC TECH 80um)/BALL BUMPER
(PAC TECH LAPLACE)

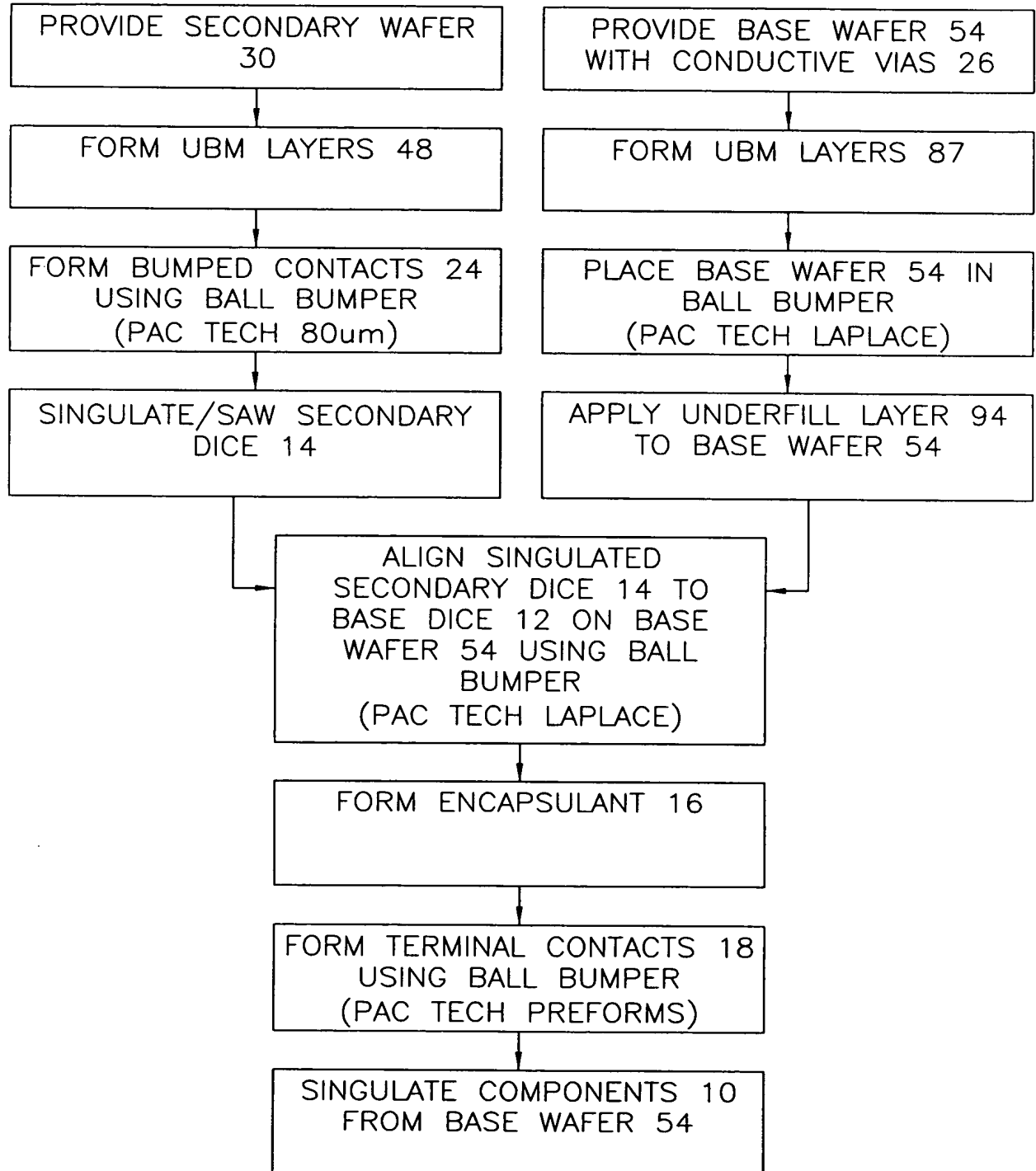


FIGURE 6C

BALL BUMPER (PAC TECH 80um)/FLIP CHIP BONDER (DATACON)

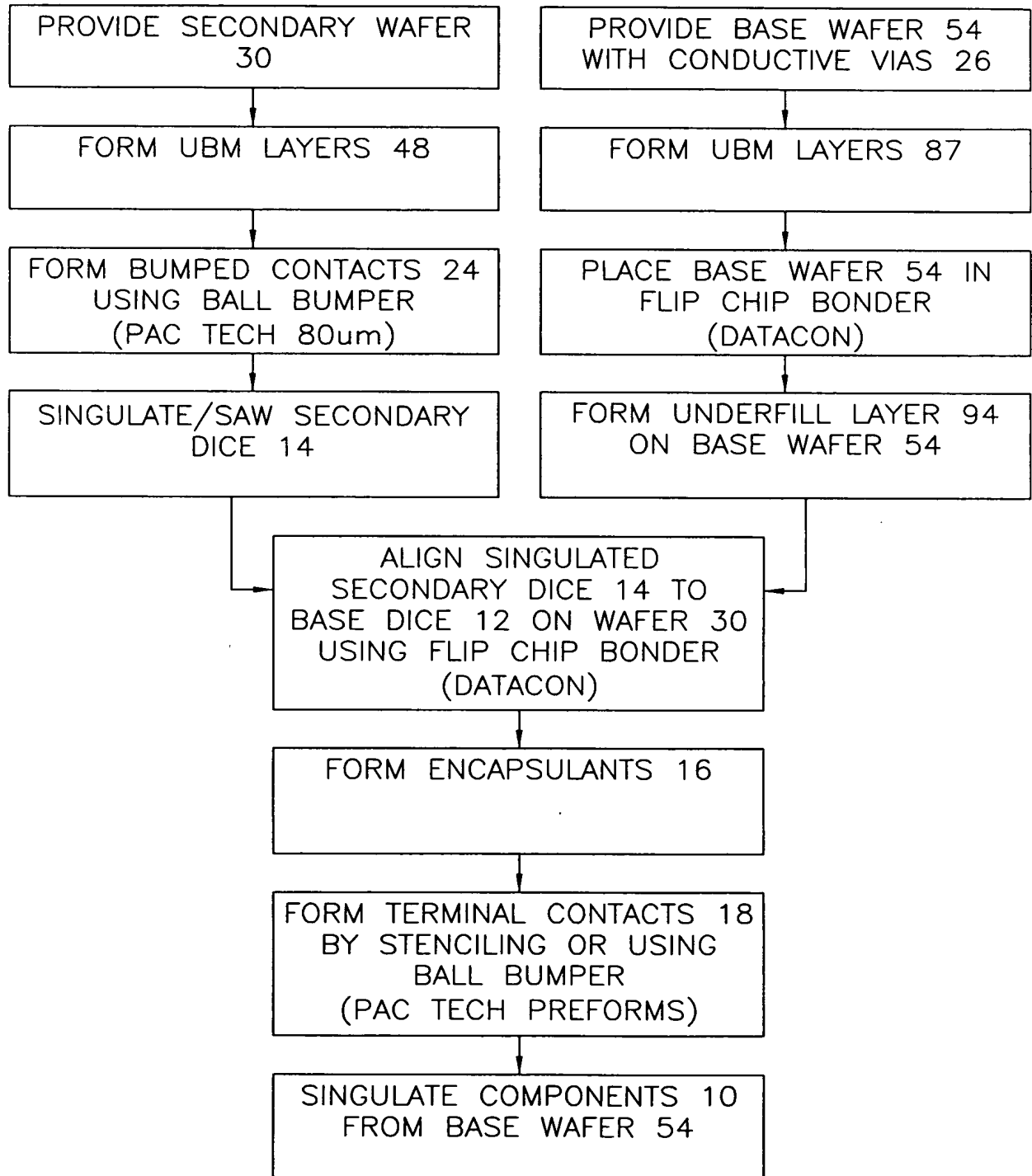


FIGURE 6D

WAFER BONDER (EVG)

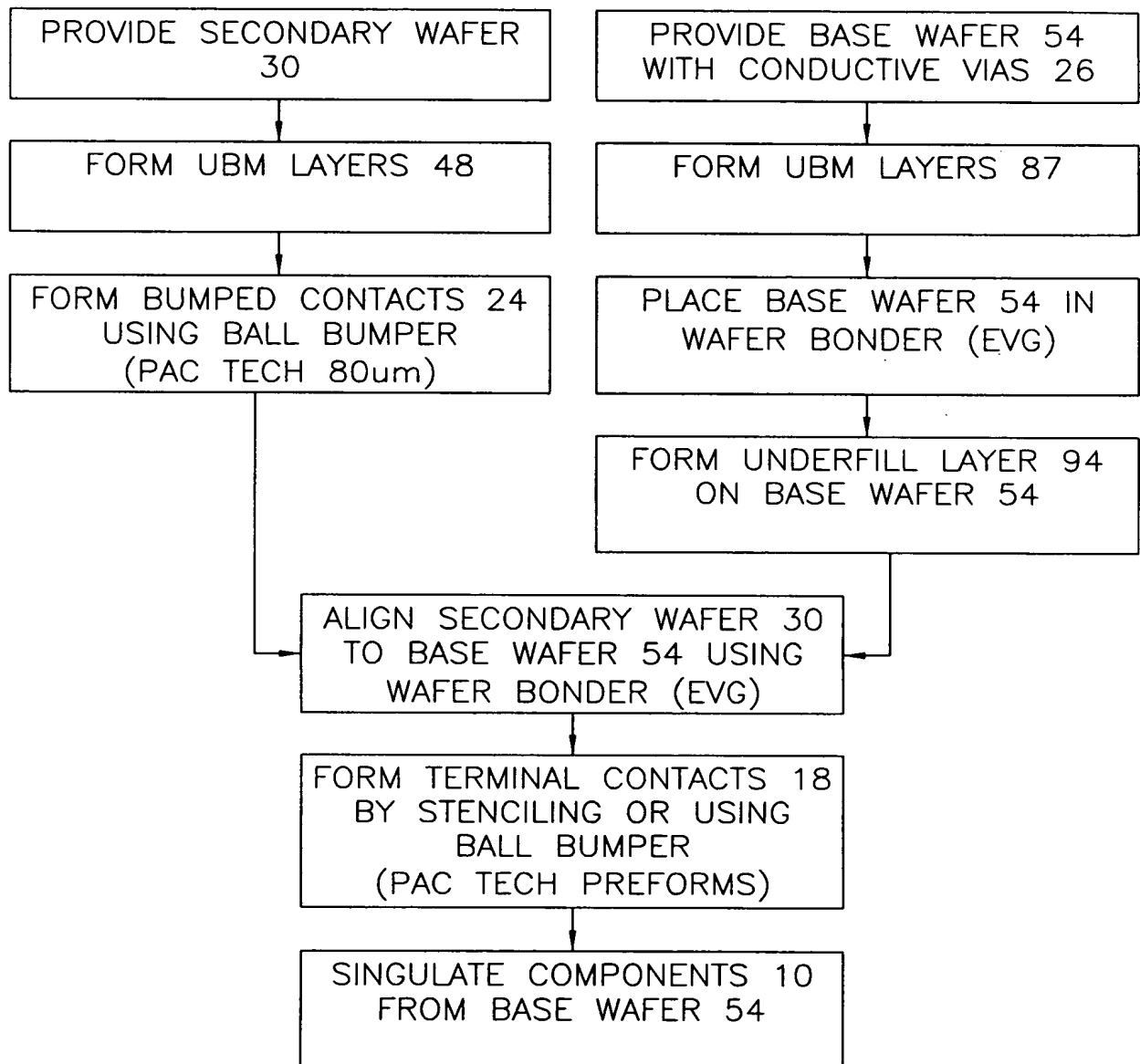


FIGURE 6E

3 DIE STACK - MINISCUS BUMPS/FLIP CHIP BONDER (M8)

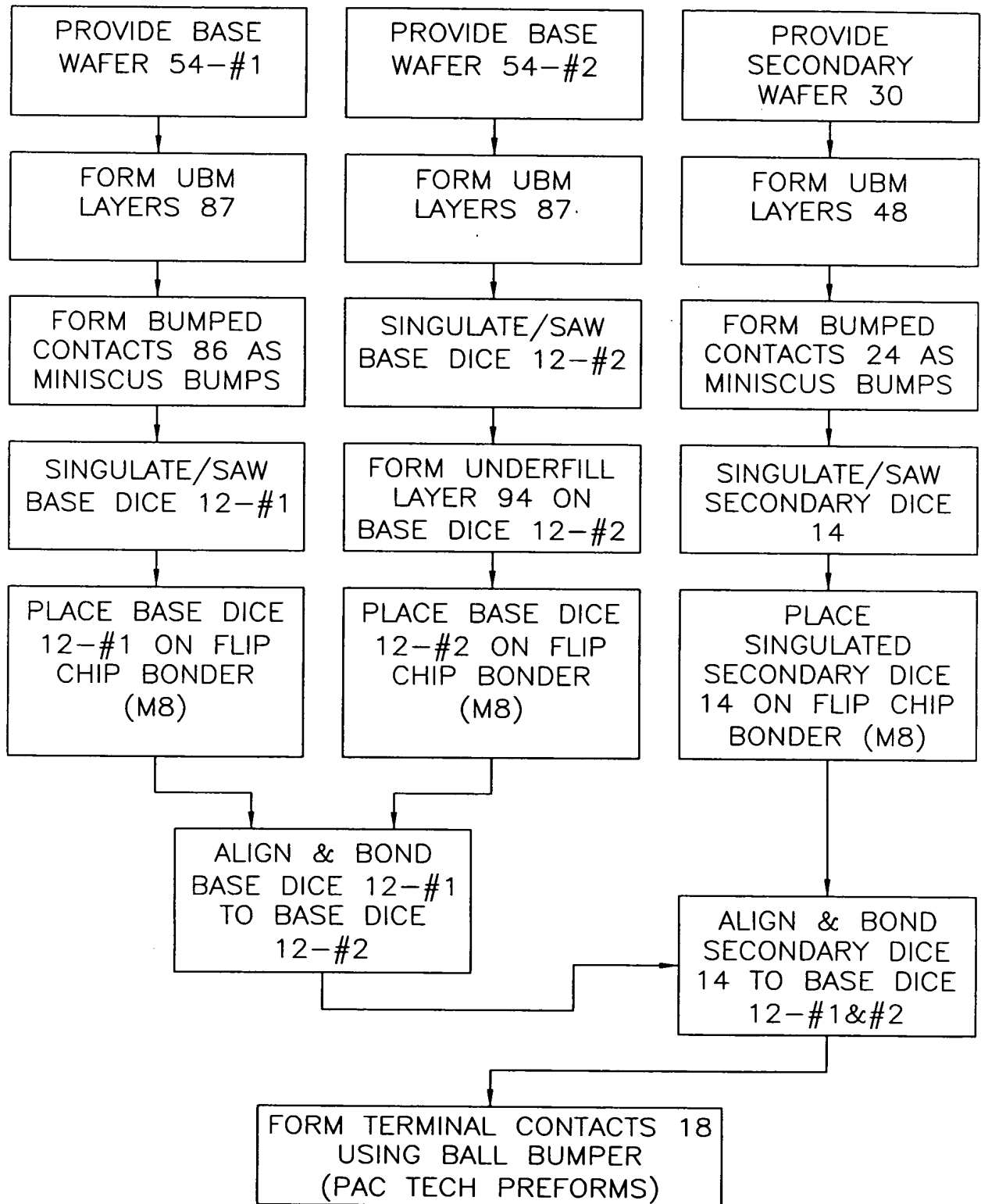


FIGURE 6F

3 DIE STACK – BALL BUMPER OR MINISCUS BUMPS/FLIP
CHIP BONDER (M8) OR (DATACON)

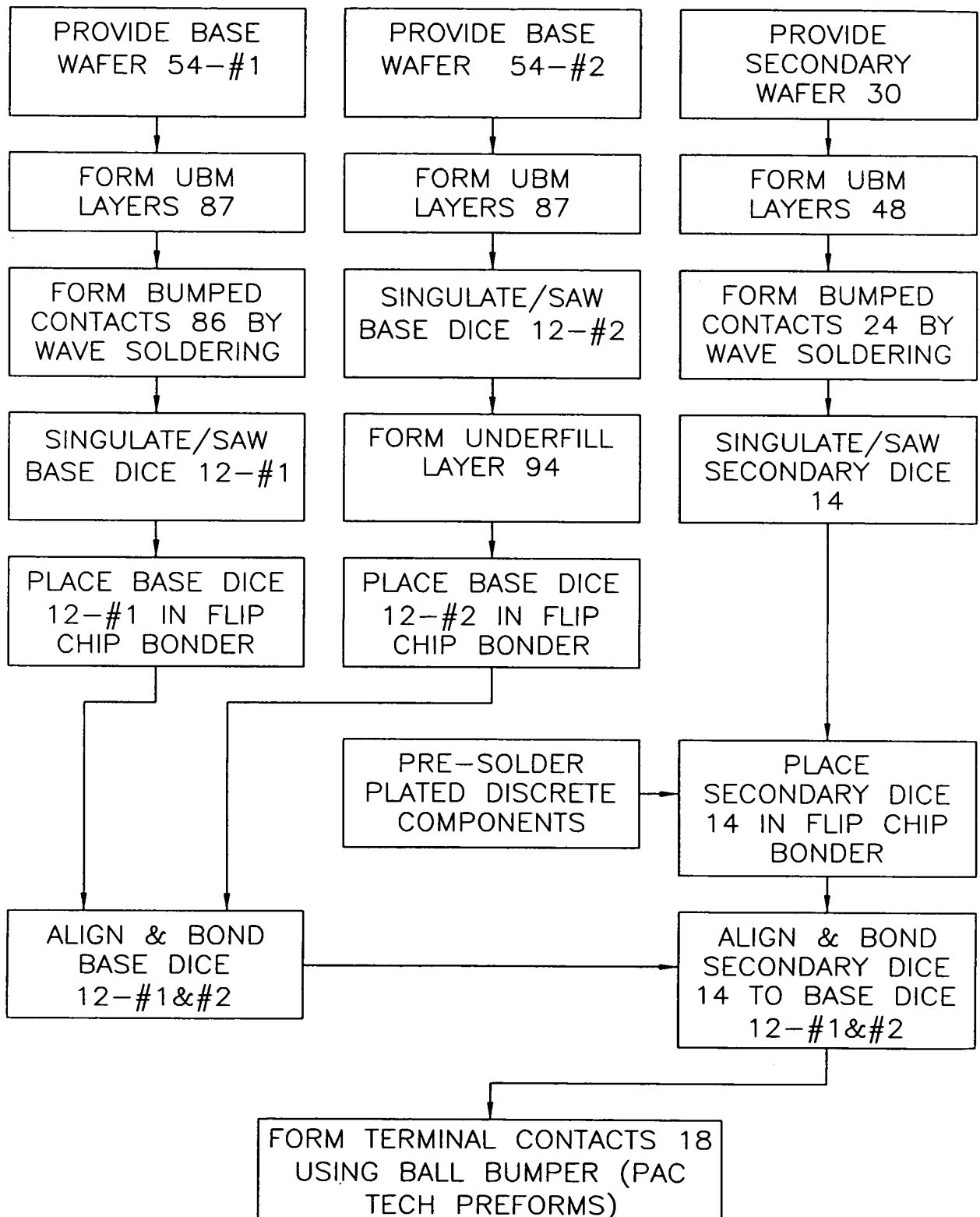


FIGURE 6G

